RX210, RX21A, RX220, RX63N, RX63T, RX111, RX64M Group

Clock Synchronous Single Master Control Software Using the SCI

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Introduction

This application note describes a clock synchronous single master control method that uses RX210, RX21A, RX220, RX63N, RX63T, RX111, RX64M Group serial communication interface (SCI) clock synchronous (three-wire method) serial communication and sample code that uses that method.

SPI mode single master control can be implemented by adding SPI slave device selection control using port control.

This sample code implements the single master basic control method that is unique to these microcontrollers. The user should implement the software required to control the slave devices using this sample code.

Software in the upper-level layer for controlling the slave device is separately available, so please obtain this from the following URL as well. When the slave device control software is added, update of this application note may not be in time. Refer to the following URL for the combination information on the latest slave device control software.

- SPI Serial EEPROM Control Software

  http://www.renesas.com/driver/spi_serial_eeprom

- SPI/QSPI Serial Flash Memory Control Software, QSPI Serial Phase Change Memory Control Software

  http://www.renesas.com/driver/spi_serial_flash

Target Devices

Target microcontroller: RX210 Group, RX21A Group, RX220 Group, RX63N Group, RX63T Group, RX111 Group. RX64M Group

Devices used in verifying operation

- Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
- Micron Technology M25P Series Serial Flash Memory Control Software 64 Mbits
- Micron Technology M45PE Series Serial Flash Memory Control Software 1 Mbit

When using this application note's sample code with another microcontroller, the code must be modified to match the specifications of the microcontroller used and tested thoroughly.

Note that the term "RX Family microcontroller" is used in this document for ease of description since the target devices come from multiple groups.

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1. Specifications

This sample program uses RX family microcontrollers SCI clock synchronous (three-wire method) serial communications to perform clock synchronous control. SPI mode single master control can be implemented by adding SPI slave device selection control using port control.

Table 1-1 lists the used peripheral functions and their uses and figure 1.1 shows an example of the use of this application.

In the following, we present an overview of these functions.

- The sample program implements a clock synchronous single master block type device driver that uses the SCI with an RX family microcontroller used as the master device.
- The microcontroller's built-in clock synchronous (three-wire method) serial communications function is used. A single channel set up by the user can also be used. Multiple channels cannot be used.
- This sample code does not support chip select control. If an SPI device is controlled, it will be necessary to provide device select control code separately.
- This sample code supports both big endian and little endian byte orders.
- Data is transferred in MSB-first format by means of software conversion.
- Only CPU transfers are supported. DMAC, EXDMAC, and DTC transfers are not supported.
- Using interrupts to start transfers is not supported.
- Operations of Single Master Transmit, Single Master Receive and Single Master Transmit/Receive are supported.

Table 1-1 Peripheral Devices and Uses

Peripheral Device	Use
SCI	Clock synchronous (three-wire method) serial communications: 1 channel (required)
Port	Used for SPI slave device selection control A number of ports corresponding to the number of devices used are needed (required). Note, however, that ports are not used in this sample code.

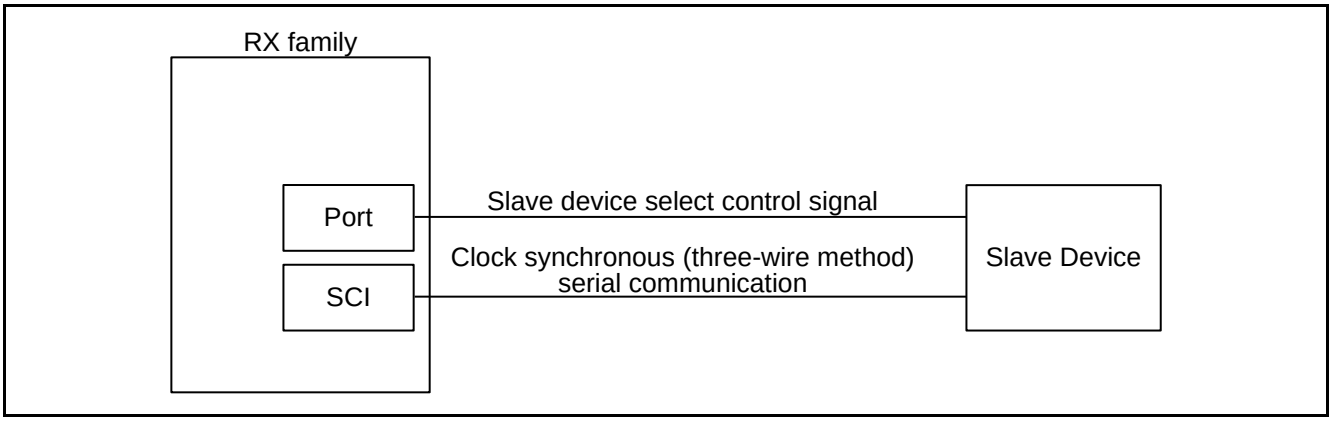


Figure 1.1 Usage Example

2. Verified Operating Conditions

Operation of this application note's sample code has been verified under the following conditions.

(1) For the RX210

Table 2-1 Verified Operating Conditions

Item	Description
Microcontroller used	RX210 Group (Program ROM: 512 KB, RAM: 64 KB)
Memory	Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
Operating frequency	ICLK: 50 MHz, PCLKB: 25 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ), Version 2.02
Board	Renesas Starter Kit for RX210

Table 2-2 Verified Operating Conditions

Item	Description
Microcontroller used	RX210 Group (Program ROM: 512 KB, RAM: 64 KB)
Memory	Micron Technology M25P Series Serial Flash Memory: 64 Mbits
Operating frequency	ICLK: 50 MHz, PCLKB: 25 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ), Version 2.01
Board	Renesas Starter Kit for RX210

Table 2-3 Verified Operating Conditions

Item	Description
Microcontroller used	RX210 Group (Program ROM: 512 KB, RAM: 64 KB)
Memory	Micron Technology M45PE Series Serial Flash Memory: 1 Mbit
Operating frequency	ICLK: 50 MHz, PCLKB: 25 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ), Version 2.01
Board	Renesas Starter Kit for RX210

(2) For the RX21A

Table 2-4 Verified Operating Conditions

Item	Description
Microcontroller used	RX21A Group (Program ROM: 512 KB, RAM: 64 KB)
Memory	Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
Operating frequency	ICLK: 50 MHz, PCLKB: 25 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ), Version 2.02
Board	HSBRX21AP-B (Hokuto Denshi Co., Ltd.)

Table 2-5 Verified Operating Conditions

Item	Description
Microcontroller used	RX21A Group (Program ROM: 512 KB, RAM: 64 KB)
Memory	Micron Technology M25P Series Serial Flash Memory: 64 Mbits
Operating frequency	ICLK: 50 MHz, PCLKB: 25 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ), Version 2.01
Board	HSBRX21AP-B (Hokuto Denshi Co., Ltd.)

Table 2-6 Verified Operating Conditions

Item	Description
Microcontroller used	RX21A Group (Program ROM: 512 KB, RAM: 64 KB)
Memory	Micron Technology M45PE Series Serial Flash Memory: 1 Mbit
Operating frequency	ICLK: 50 MHz, PCLKB: 25 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ), Version 2.01
Board	HSBRX21AP-B (Hokuto Denshi Co., Ltd.)

(3) For the RX220

Table 2-7 Verified Operating Conditions

Item	Description
Microcontroller used	RX220 Group (Program ROM: 256 KB, RAM: 16 KB)
Memory	Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
Operating frequency	ICLK: 32 MHz, PCLKB: 32 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.01.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ), Version 2.02
Board	Renesas Starter Kit for RX220

Table 2-8 Verified Operating Conditions

Item	Description
Microcontroller used	RX220 Group (Program ROM: 256 KB, RAM: 16 KB)
Memory	Micron Technology M25P Series Serial Flash Memory: 64 Mbits
Operating frequency	ICLK: 32 MHz, PCLKB: 32 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.01.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ), Version 2.01
Board	Renesas Starter Kit for RX220

Table 2-9 Verified Operating Conditions

Item	Description
Microcontroller used	RX220 Group (Program ROM: 256 KB, RAM: 16 KB)
Memory	Micron Technology M45PE Series Serial Flash Memory: 1 Mbit
Operating frequency	ICLK: 32 MHz, PCLKB: 32 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.01.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ), Version 2.01
Board	Renesas Starter Kit for RX220

(4) For the RX63N

Table 2-10 Verified Operating Conditions

Item	Description
Microcontroller used	RX63N Group (Program ROM: 1 MB, RAM: 128 KB)
Memory	Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
Operating frequency	ICLK: 96 MHz, PCLKB: 48 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ), Version 2.02
Board	Renesas Starter Kit for RX63N

Table 2-11 Verified Operating Conditions

Item	Description
Microcontroller used	RX63N Group (Program ROM: 1 MB, RAM: 128 KB)
Memory	Micron Technology M25P Series Serial Flash Memory: 64 Mbits
Operating frequency	ICLK: 96 MHz, PCLKB: 48 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ), Version 2.01
Board	Renesas Starter Kit for RX63N

Table 2-12 Verified Operating Conditions

Item	Description
Microcontroller used	RX63N Group (Program ROM: 1 MB, RAM: 128 KB)
Memory	Micron Technology M45PE Series Serial Flash Memory: 1 Mbit
Operating frequency	ICLK: 96 MHz, PCLKB: 48 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation High-performance embedded Workshop Version 4.09.00.007
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 1.2.1.0)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ), Version 2.01
Board	Renesas Starter Kit for RX63N

(5) For the RX63T

Table 2-13 Verified Operating Conditions

Item	Description
Microcontroller used	RX63T Group (Program ROM: 512 KB, RAM: 48 KB)
Memory	Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
Operating frequency	ICLK: 96 MHz, PCLKB: 48 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation CubeSuite+ V2.00.00
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.00.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ), Version 2.02
Board	Renesas Starter Kit for RX63T

Table 2-14 Verified Operating Conditions

Item	Description
Microcontroller used	RX63T Group (Program ROM: 512 KB, RAM: 48 KB)
Memory	Micron Technology M25P Series Serial Flash Memory: 64 Mbits
Operating frequency	ICLK: 96 MHz, PCLKB: 48 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation CubeSuite+ V2.00.00
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.00.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ), Version 2.01
Board	Renesas Starter Kit for RX63T

Table 2-15 Verified Operating Conditions

Item	Description
Microcontroller used	RX63T Group (Program ROM: 512 KB, RAM: 48 KB)
Memory	Micron Technology M45PE Series Serial Flash Memory: 1 Mbit
Operating frequency	ICLK: 96 MHz, PCLKB: 48 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation CubeSuite+ V2.00.00
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.00.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01.R01
Software	Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ), Version 2.01
Board	Renesas Starter Kit for RX63T

(6) For the RX111

Table 2-16 Verified Operating Conditions

Item	Description
Microcontroller used	RX111 Group (Program ROM: 128KB, RAM: 16KB)
Memory	Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
Operating frequency	ICLK: 32 MHz, PCLKB: 32 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation CubeSuite+ V2.01.00
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.01.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01 R05
Software	Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ), Version 2.03 R01
Board	Renesas Starter Kit for RX111

Table 2-17 Verified Operating Conditions

Item	Description
Microcontroller used	RX111 Group (Program ROM: 128KB, RAM: 16KB)
Memory	Micron Technology M25P Series Serial Flash Memory: 64 Mbits
Operating frequency	ICLK: 32 MHz, PCLKB: 32 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation CubeSuite+ V2.01.00
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.01.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01 R05
Software	Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ), Version 2.02 R01
Board	Renesas Starter Kit for RX111

Table 2-18 Verified Operating Conditions

Item	Description
Microcontroller used	RX111 Group (Program ROM: 128KB, RAM: 16KB)
Memory	Micron Technology M45PE Series Serial Flash Memory: 1 Mbit
Operating frequency	ICLK: 32 MHz, PCLKB: 32 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation CubeSuite+ V2.01.00
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.01.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.01 R05
Software	Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ), Version 2.02 R01
Board	Renesas Starter Kit for RX111

(7) For the RX64M

Table 2-19 Verified Operating Conditions

Item	Description
Microcontroller used	RX64M Group (Program ROM: 4MB, RAM: 512KB)
Memory	Renesas Electronics Corporation R1EX25xxx Series SPI Serial EEPROM
Operating frequency	ICLK: 120 MHz, PCLKB: 60 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation e2studio V3.1.0.24
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.01.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.02
Software	Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ), Version 2.03
Board	Renesas Starter Kit for RX64M

Table 2-20 Verified Operating Conditions

Item	Description
Microcontroller used	RX64M Group (Program ROM: 4MB, RAM: 512KB)
Memory	Micron Technology M25P Series Serial Flash Memory: 64 Mbits
Operating frequency	ICLK: 120 MHz, PCLKB: 60 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation e2studio V3.1.0.24
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.01.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.02
Software	Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ), Version 2.02
Board	Renesas Starter Kit for RX64M

Table 2-21 Verified Operating Conditions

Item	Description
Microcontroller used	RX64M Group (Program ROM: 4MB, RAM: 512KB)
Memory	Micron Technology M45PE Series Serial Flash Memory: 1 Mbit
Operating frequency	ICLK: 120 MHz, PCLKB: 60 MHz
Operating voltage	3.3 V
Integrated development environment	Renesas Electronics Corporation e2studio V3.1.0.24
C compiler	Renesas Electronics Corporation RX Family C/C++ Compiler Package (Toolchain 2.01.00)
	Compiler options The integrated development environment default settings*1 are used. Note: 1. Optimization level: 2, optimization method: Size priority
Endian order	Big endian / Little endian
Sample code version number	Ver. 2.02
Software	Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ), Version 2.02
Board	Renesas Starter Kit for RX64M

3. Related Application Notes

Related application notes are listed below. Refer to these when using this application note.

- Renesas R1EX25xxx Series Serial EEPROM Control Software (R01AN0565EJ)
- Micron Technology M25P Series Serial Flash Memory Control Software (R01AN0566EJ)
- Micron Technology M45PE Series Serial Flash Memory Control Software (R01AN0567EJ)
- Micron Technology N25Q Serial NOR Flash Memory Control Software (R01AN1528EJ)
- Micron Technology P5Q Serial Phase Change Memory Control Software (R01AN1439EJ)
- Spansion S25FLxxxS MirrorBit® Flash Non-Volatile Memory Control Software (R01AN1529EJ)
- Macronix International MX25/66L Family Serial NOR Flash Memory Control Software (R01AN1967EJ)

4. Hardware Description

4.1 Reference Circuit

Figure 4.1 shows the device connection circuit diagram.

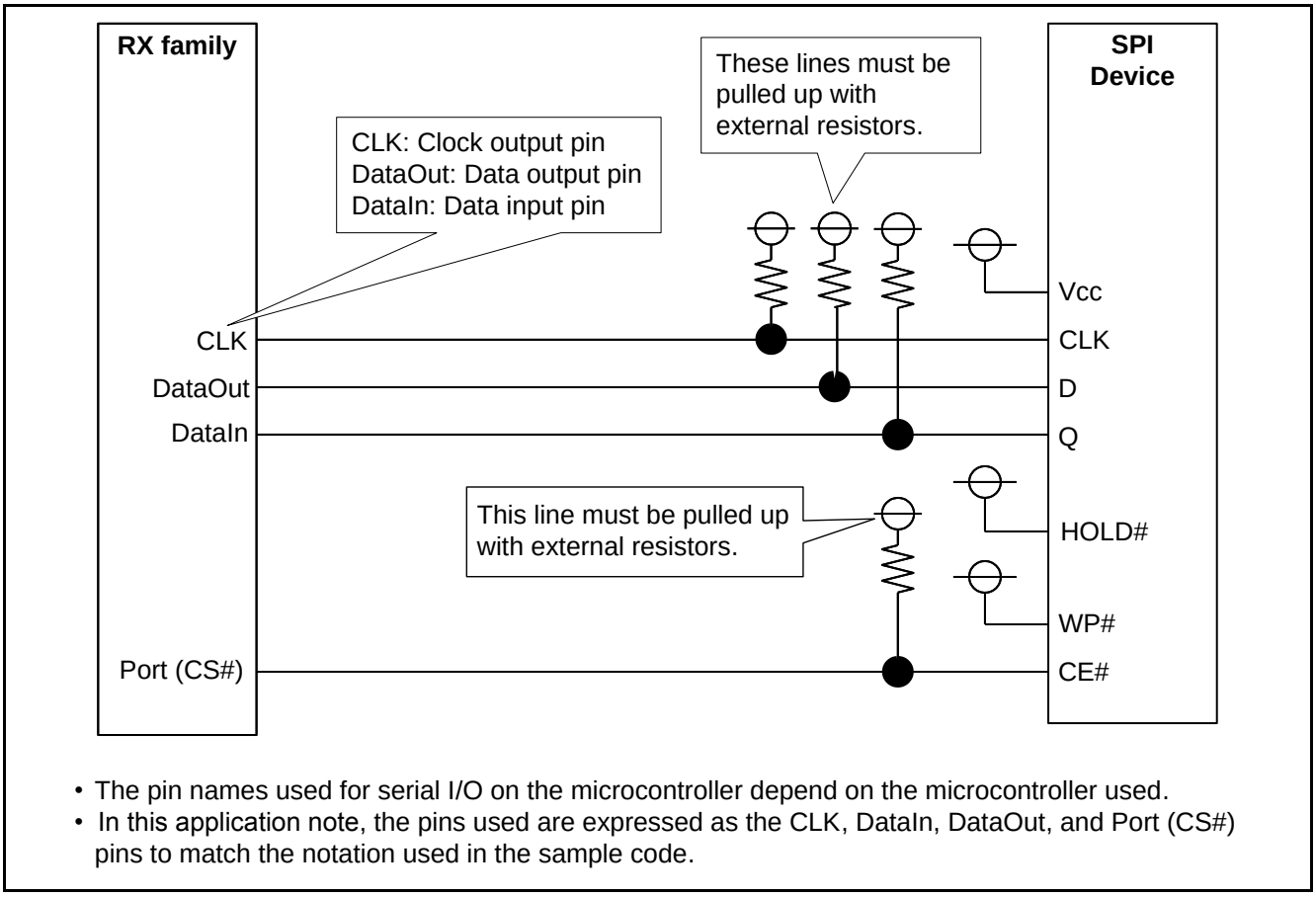


Figure 4.1 Connection Between RX Family Microcontrollers SCI and SPI Slave Device

4.2 List of Pins

The following table lists the pins used and their functions.

Table 4-1 Pins and Usage

Pin Name	I/O	Description
SCK (CLK in figure 4.1)	Output	Clock output
TxD (DataOut in figure 4.1)	Output	Master data output
RxD (DataIn in figure 4.1)	Input	Master data input
Port (Port(CS#) in figure 4.1)	Output	Slave device select output Note, however, that this pin is not handled by this sample code.

5. Software Description

5.1 Operation Overview

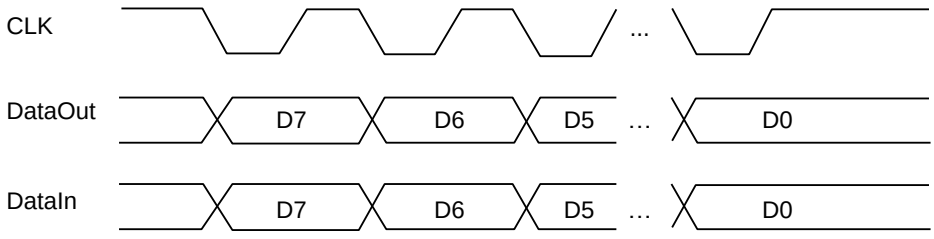
This sample code uses the SCI module's clock synchronous (three-wire method) serial communication function to implement clock synchronous single master control.

This sample code implements the following control operation.

- Control of data transmit/receive operations in clock synchronous operation (using an internal clock).

5.1.1 Timing Generated in Clock Synchronous Operation

This sample code generates the SPI mode 3 (CPOL = 1, CPHA = 1) timing shown in figure 5.1, which is required for SPI slave device control.



- For microcontroller to SPI slave device transmission: Transmit data output starts on the falling edge of the transfer clock
- For SPI slave device to microcontroller reception: Receive data input is acquired on the rising edge of the transfer clock
- Data is transferred MSB first.

The CLK pin is held at the high level when no transfer is being performed.

Figure 5.1 Timing Settings for Clock Synchronous Operation

Check the microcontroller and SPI slave device datasheets for the serial clock frequencies that can be used.

5.1.2 SPI Slave Device CE# Pin Control

This sample code does not control the SPI slave device CE# pin. To control an SPI device, the user must provide SPI slave device CE# pin control separately.

As the control method, we recommend connecting to a microcontroller port and controlling the SPI device with the microcontroller general-purpose port output.

Also, the application must provide time from the fall of the SPI device CE# (microcontroller port CS#) signal to the fall of the SPI device CLK (the microcontroller CLK) signal.

Similarly, the application must provide time from the rise of the SPI device CLK (the microcontroller CLK) signal to the rise of the SPI device CE# (microcontroller port CS#) signal.

Check the SPI device data sheet, and implement the application with software wait times appropriate for the system.

5.2 Software Control Outline

5.2.1 Software Structure

This sample code implements a single master basic control method that is unique to the microcontroller.

In particular, this sample code implements control that uses SPI mode 3 (CPOL = 1, CPHA = 1) without control of the SPI slave device CE# pin.

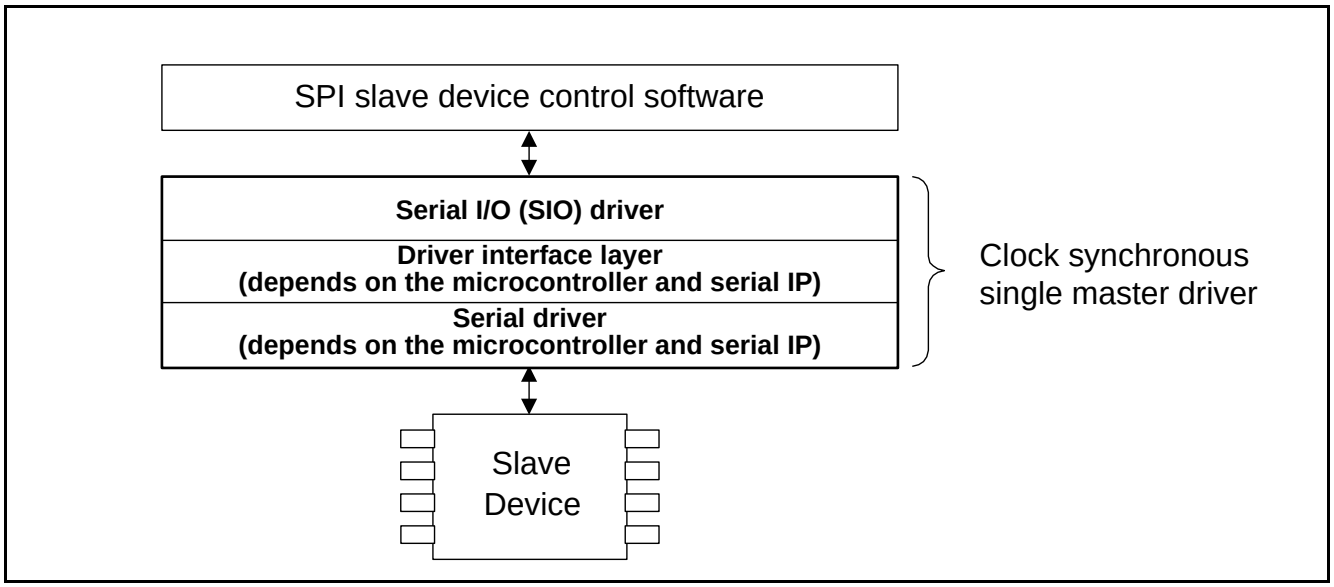


Figure 5.2 Software Structure

The user must implement slave device access by referring to the functions shown in section 5.8, State Transition Diagram, and section 5.9, Function Specifications.

Refer to the previously mentioned section 3, Related Application Notes for specific application examples.

5.2.2 Relationship Between Data Buffers and Transmit/Receive Data

This sample code is a block type device driver and passes the transmit or receive data pointer as an argument. The relationship between the data ordering in the data buffer in RAM and the transmit/receive order is shown below and this sample code both transmits in the order data is stored in the transmit buffer and writes data to the receive data buffer in the order received regardless of the endian order or serial communication function used.

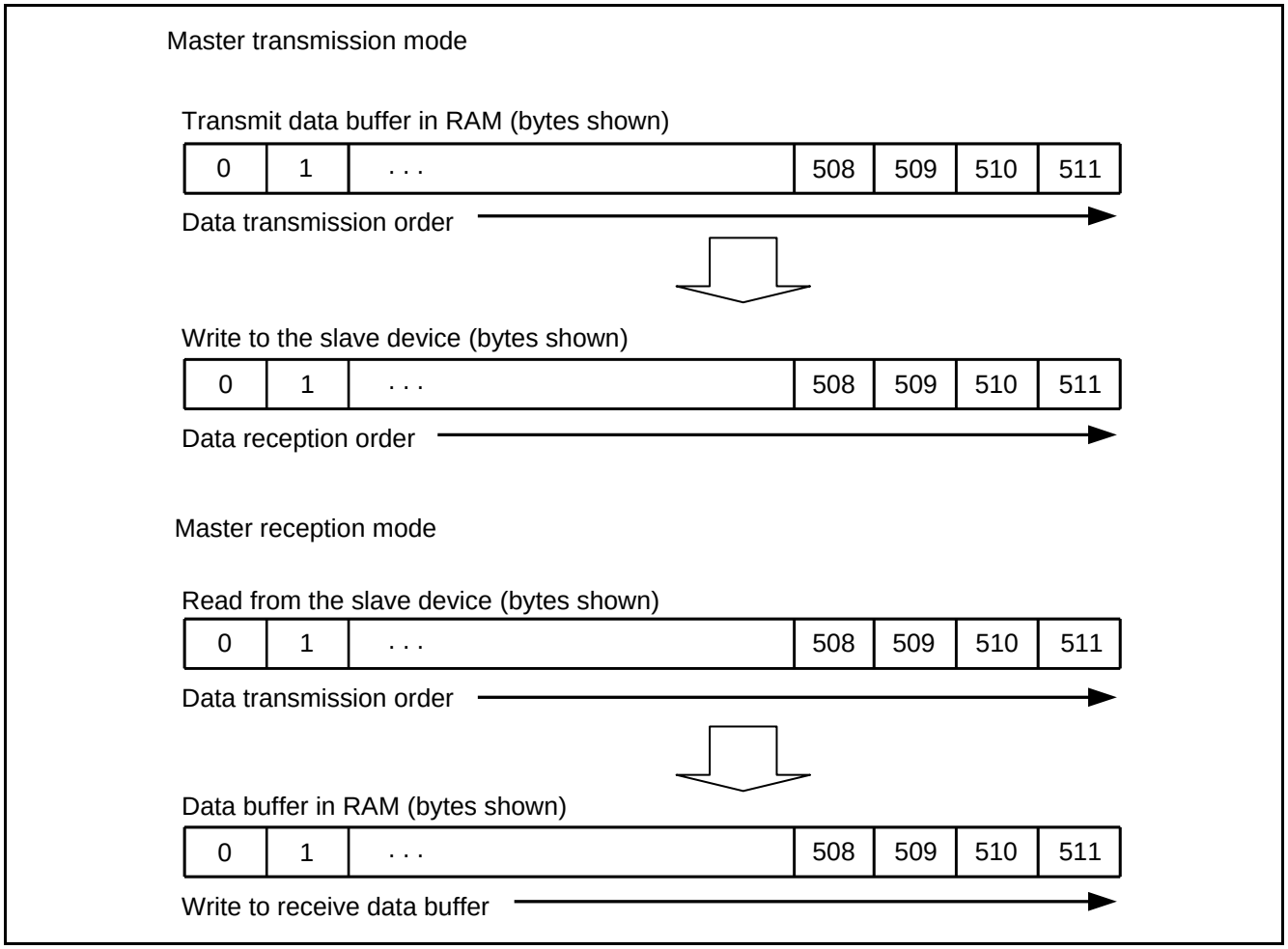


Figure 5.3 Relationship Between Data Buffers and Transmit/Receive Data

5.3 Size of Required Memory

The following table lists the memory requirements.

The memory sizes listed in table 5.1 apply when SIO_OPTION_1 is selected with the operating mode definition used in section 6.2.2, R_SIO_sci.h (1). The memory requirements differ depending on the selected definition.

(1) For the RX210

Table 5-1 Memory Requirements

Memory Used	Size	Remarks
ROM	1,416 bytes (little endian)	R_SIO_sci_rx.c
RAM	0 byte (little endian)	R_SIO_sci_rx.c
Maximum user stack usage	64 bytes	
Maximum interrupt stack usage	—	

Note: The memory requirements may differ with the version of the C compiler used or with the compiler options specified.
The above memory requirements may differ depending on the endian order selected.

(2) For the RX21A

Table 5-2 Memory Requirements

Memory Used	Size	Remarks
ROM	1,371 bytes (little endian)	R_SIO_sci_rx.c
RAM	0 byte (little endian)	R_SIO_sci_rx.c
Maximum user stack usage	64 bytes	
Maximum interrupt stack usage	—	

Note: The memory requirements may differ with the version of the C compiler used or with the compiler options specified.
The above memory requirements may differ depending on the endian order selected.

(3) For the RX220

Table 5-3 Memory Requirements

Memory Used	Size	Remarks
ROM	1,377 bytes (little endian)	R_SIO_sci_rx.c
RAM	0 byte (little endian)	R_SIO_sci_rx.c
Maximum user stack usage	64 bytes	
Maximum interrupt stack usage	—	

Note: The memory requirements may differ with the version of the C compiler used or with the compiler options specified.
The above memory requirements may differ depending on the endian order selected.

(4) For the RX63N

Table 5-4 Memory REQUIREMENTS

Memory Used	Size	Remarks
ROM	1,398 bytes (little endian)	R_SIO_sci_rx.c
RAM	0 byte (little endian)	R_SIO_sci_rx.c
Maximum user stack usage	64 bytes	
Maximum interrupt stack usage	—	

Note: The memory requirements may differ with the version of the C compiler used or with the compiler options specified.
The above memory requirements may differ depending on the endian order selected.

(5) For the RX63T

Table 5-5 Memory Requirements

Memory Used	Size	Remarks
ROM	1,482 bytes (little endian)	R_SIO_sci_rx.c
RAM	0 byte (little endian)	R_SIO_sci_rx.c
Maximum user stack usage	68 bytes	
Maximum interrupt stack usage	—	

Note: The memory requirements may differ with the version of the C compiler used or with the compiler options specified.
The above memory requirements may differ depending on the endian order selected.

(6) For the RX111

Table 5-6 Memory Requirements

Memory Used	Size	Remarks
ROM	1,278 bytes (little endian)	R_SIO_sci_rx.c
RAM	0 byte (little endian)	R_SIO_sci_rx.c
Maximum user stack usage	68 bytes	
Maximum interrupt stack usage	—	

Note: The memory requirements may differ with the version of the C compiler used or with the compiler options specified.
The above memory requirements may differ depending on the endian order selected.

(7) For the RX64M

Table 5-7 Memory Requirements

Memory Used	Size	Remarks
ROM	1,723 bytes (little endian)	R_SIO_sci_rx.c
RAM	0 byte (little endian)	R_SIO_sci_rx.c
Maximum user stack usage	72 bytes	
Maximum interrupt stack usage	—	

Note: The memory requirements may differ with the version of the C compiler used or with the compiler options specified.
The above memory requirements may differ depending on the endian order selected.

The ROM size has increased than previous version because of adding transmit/receive operation.

5.4 File Configuration

The following table lists the files used by the sample code. Note that the files automatically generated by the integrated development environment are not included.

Table 5-8 File Configuration

\an_r01an1229ej0107_rx_serial		<DIR>	Sample code folder
r01an1229ej0107_rx.pdf			Application note
\source		<DIR>	Program folder
\com		<DIR>	Common function folder
Note 1	mtl_com.c		Common function definitions
	mtl_com.h.common		Common header file
	mtl_com.h.RX		Common functions header file
	mtl_endi.c		Common files (endian setting related)
	mtl_mem.c		Common files (Standard library functions)
	mtl_os.c	mtl_os.h	Common files (Standard library functions)
	mtl_str.c		Common files (Standard library functions)
	mtl_tim.c	mtl_tim.h	Common files (Loop timer related)
	mtl_tim.h.sample		Sample loop timer settings
\r_sio_sci_rx		<DIR>	Folder for clock synchronous single master control software using the SCI
	R_SIO.h		Header file
	R_SIO_sci.h.rx21a		Interface module common definitions (RX21A)
	R_SIO_sci.h.rx63n		Interface module common definitions (RX63N)
	R_SIO_sci.h.rx63t		Interface module common definitions (RX63T)
	R_SIO_sci.h.rx64m		Interface module common definitions (RX64M)
	R_SIO_sci.h.rx111		Interface module common definitions (RX111)
	R_SIO_sci.h.rx210		Interface module common definitions (RX210)
	R_SIO_sci.h.rx220		Interface module common definitions (RX220)
	R_SIO_sci_rx.c		Interface module

Note: 1. The files held in the com folder are also used by the slave device control software. Use the latest versions of these files.

5.5 List of Constants

5.5.1 Return Values

The following table lists the return values used in the sample code.

Table 5-9 Return Values

Constant Name	Value	Description
SIO_OK	(error_t)(0)	Successful operation
SIO_ERR_PARAM	(error_t)(-1)	Parameter error
SIO_ERR_HARD	(error_t)(-2)	Hardware error
SIO_ERR_OTHER	(error_t)(-7)	Other error

5.5.2 Definitions

The following table lists the values for certain definitions used in the sample code.

Table 5-10 Return Values

Constant Name	Value	Description
SIO_LOG_ERR	1	Log type: Error
SIO_TRUE	(uint8_t)0x01	Flag "ON"
SIO_FALSE	(uint8_t)0x00	Flag "OFF"
SIO_HI	(uint8_t)0x01	Port "H"
SIO_LOW	(uint8_t)0x00	Port "L"
SIO_OUT	(uint8_t)0x01	Port output setting
SIO_IN	(uint8_t)0x00	Port input setting
SIO_TX_WAIT	(uint16_t)50000	SIO transmission completion waiting time 50000* 1 us = 50 ms
SIO_RX_WAIT	(uint16_t)50000	SIO reception completion waiting time 50000* 1 us = 50 ms
SIO_DMA_TX_WAIT	(uint16_t)50000	DMA transmission completion waiting time 50000* 1 us = 50 ms
SIO_DMA_RX_WAIT	(uint16_t)50000	DMA reception completion waiting time 50000* 1 us = 50 ms
SIO_T_SIO_WAIT	(uint16_t)MTL_T_1US	SIO transmission&reception completion waiting polling time
SIO_T_DMA_WAIT	(uint16_t)MTL_T_1US	DMA transmission&reception completion waiting polling time
SIO_T_BRR_WAIT	(uint16_t)MTL_T_10US	BRR setting wait time

5.6 Structures and Unions

The structures used in the sample code are shown below.

```
/* uint32_t <-> uint8_t conversion */
typedef union {
  uint32_t  ul;
  uint8_t uc[4];
} SIO_EXCHG_LONG;                          /* total 4byte                */

/* uint16_t <-> uint8_t conversion */
typedef union {
  uint16_t  us;
  uint8_t uc[2];
} SIO_EXCHG_SHORT;                         /* total 2byte                */
```

5.7 List of Functions

The following table lists the functions in the sample code.

Table 5-11 List of Functions

Function Name	Outline
R_SIO_Init_Driver()	Driver initialization
R_SIO_Disable()	Disables serial I/O
R_SIO_Enable()	Enables serial I/O
R_SIO_Open_Port()	Releases serial I/O
R_SIO_Tx_Data()	Transmits serial I/O data
R_SIO_Rx_Data()	Receives serial I/O data
R_SIO_TRx_Data()	Transmits/Receives serial I/O data

5.8 State Transition Diagram

Figure 5.4 shows the state transition diagram for this system.

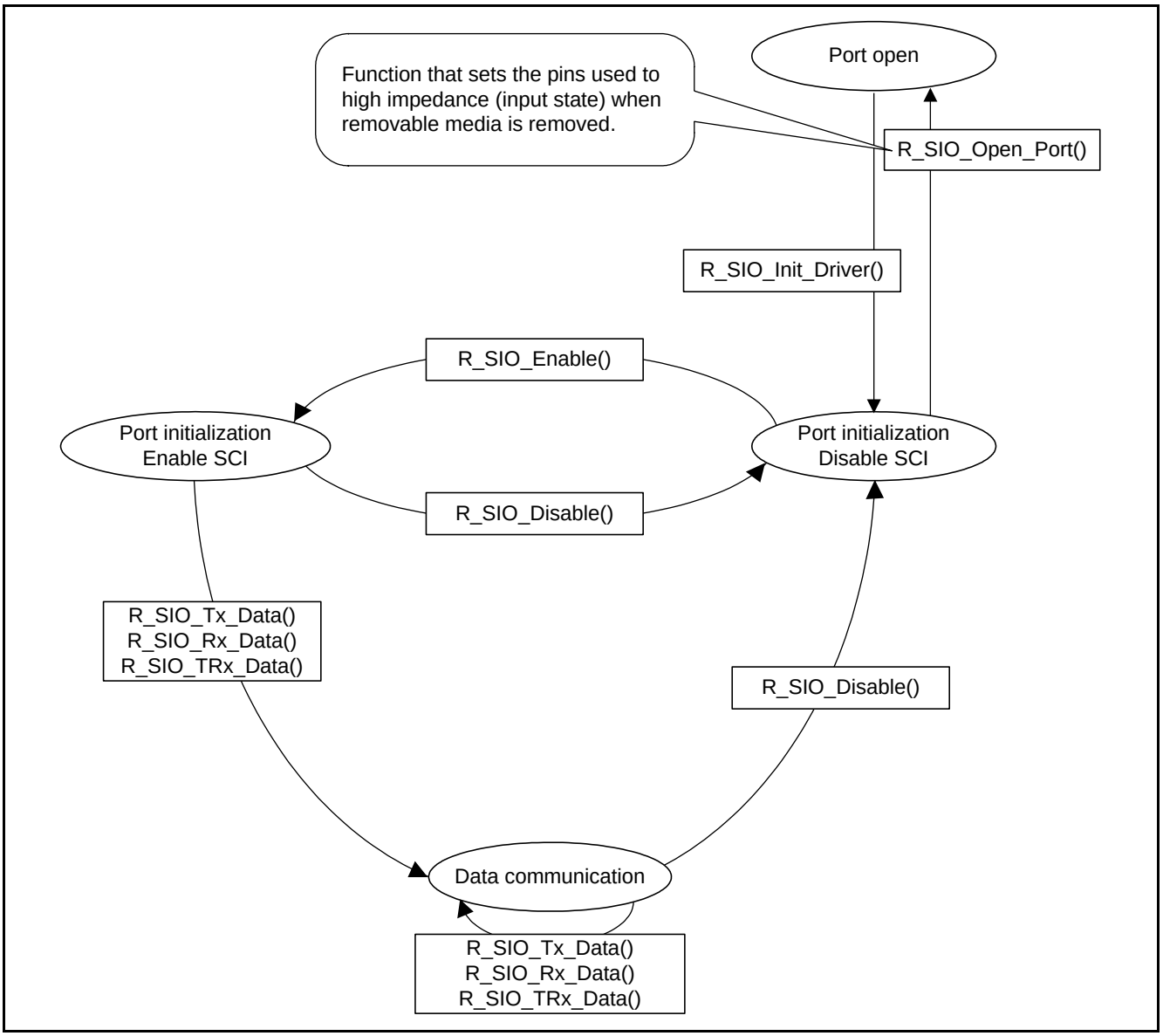


Figure 5.4 State Transition Diagram

5.9 Function Specifications

5.9.1 Driver Initialization Processing

R_SIO_Init_Driver

Outline	Driver initialization processing
Header	R_SIO.h, R_SIO_sci.h, mtl_com.h
Declaration	error_t R_SIO_Init_Driver(void)
Description	• Initializes the driver. Disables the serial I/O function and sets the pins to their port function. • This function must be called exactly once when the system starts. • Set the slave device select control signal to the high level before calling this function.
Arguments	None
Return value	SIO_OK ; Successful operation
Notes	The following processing, which takes into account the previous state, is performed. • The function R_SIO_Disable() is called.

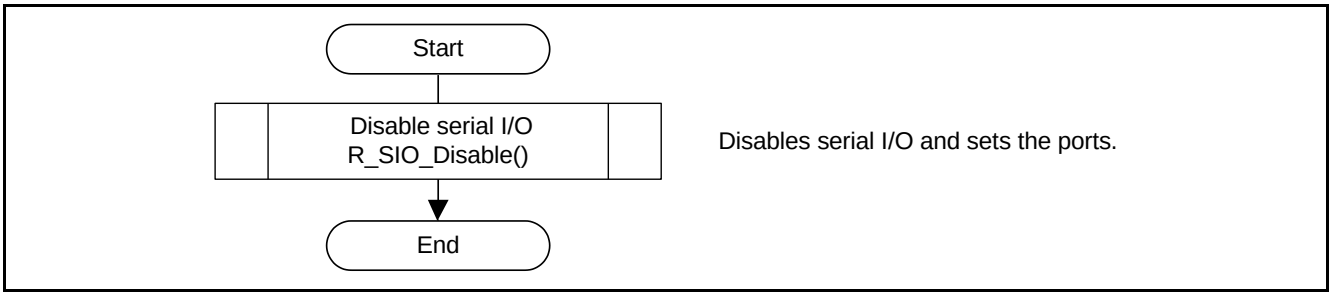


Figure 5.5 Driver Initialization Processing Outline

5.9.2 Serial I/O Disable Setup Processing

R_SIO_Disable

Outline	Serial I/O disable setup processing
Header	R_SIO.h, R_SIO_sci.h, mtl_com.h
Declaration	error_t R_SIO_Disable(void)
Description	• Disables the serial I/O function and sets the pins to their port function. Disables serial I/O. Sets the pins used for serial I/O to their port function. • Set the slave device select control signal to the high level before calling this function.
Arguments	None
Return value	SIO_OK ; Successful operation
Notes	• The SCI module stop state is canceled temporarily to write to the SCI related registers. After setting the SCI related registers, the module is set back to the module stop state. • If not used, this function can be called to disable the serial I/O function.

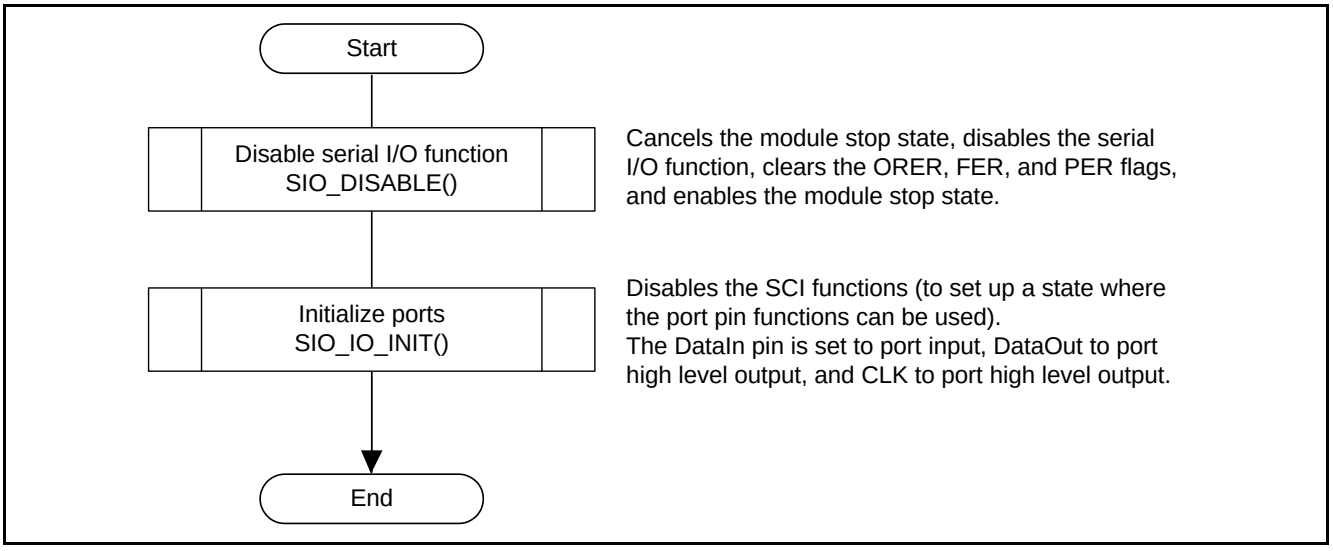


Figure 5.6 Serial I/O Disable Setup Processing Outline

5.9.3 Serial I/O Enable Setup Processing

R_SIO_Enable

Outline	Serial I/O enable setup processing
Header	R_SIO.h, R_SIO_sci.h, mtl_com.h
Declaration	error_t R_SIO_Enable(uint8_t BrgData)
Description	• Enables the serial I/O function and sets the bit rate. Sets the pins used by serial I/O to their port function. Enables serial I/O and sets the bit rate. • Call this function only after calling R_SIO_Disable(). • This function must be called before performing either serial I/O data transmission or serial I/O data reception. • Use this function to change the bit rate. But before doing that, first call the disable serial I/O function.
Arguments	uint8_t BrgData ; Bit rate setting
Return value	SIO_OK ; Successful operation
Notes	• This function sets the serial I/O module used to the module stop canceled state. • The software wait (10 µs) is the wait time required to set the bit rate.

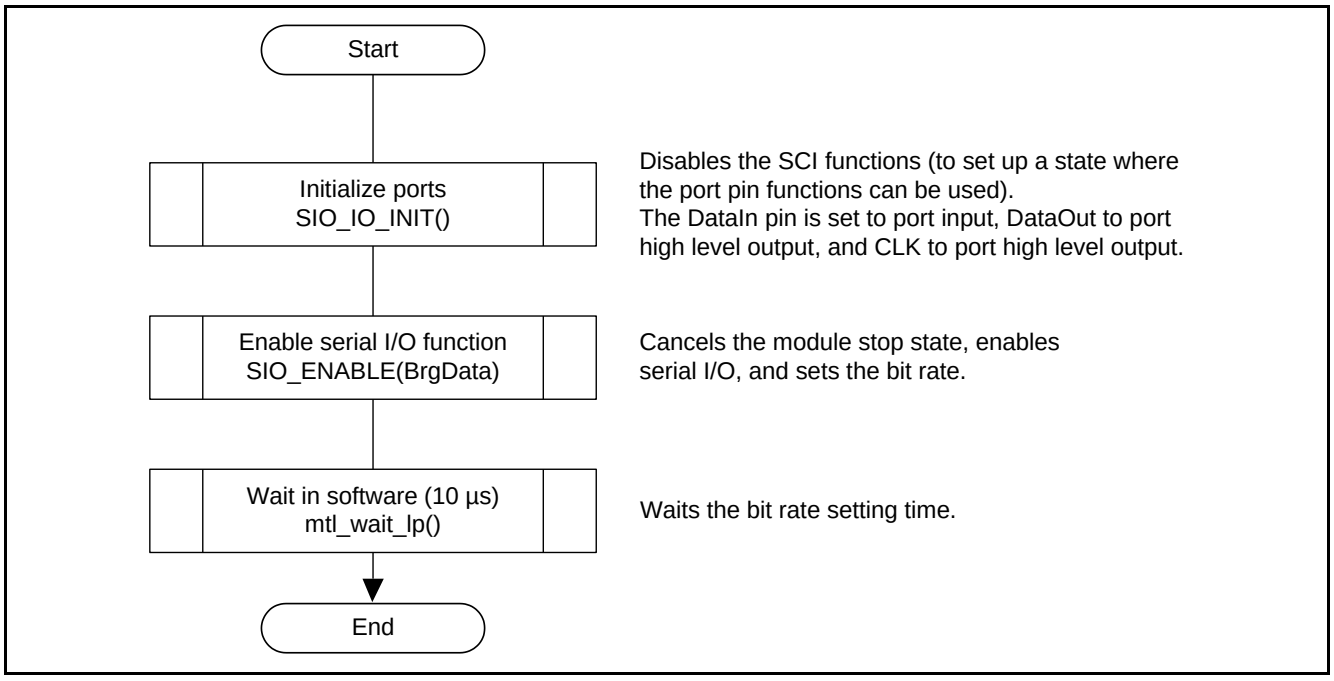


Figure 5.7 Serial I/O Enable Setup Processing Outline

5.9.4 Serial I/O Open Setup Processing

R_SIO_Open_Port

Outline	Serial I/O open setup processing
Header	R_SIO.h, R_SIO_sci.h, mtl_com.h
Declaration	error_t R_SIO_Open_Port(void)
Description	• Sets the pins used for serial I/O to open (the input state). • Set the slave device select control signal to the high level before calling this function.
Arguments	None
Return value	SIO_OK ; Successful operation
Notes	This function is provided for inserting and removing removable media. Use this function before inserting or removing removable media. Perform the serial I/O disable setup processing before removing removable media.

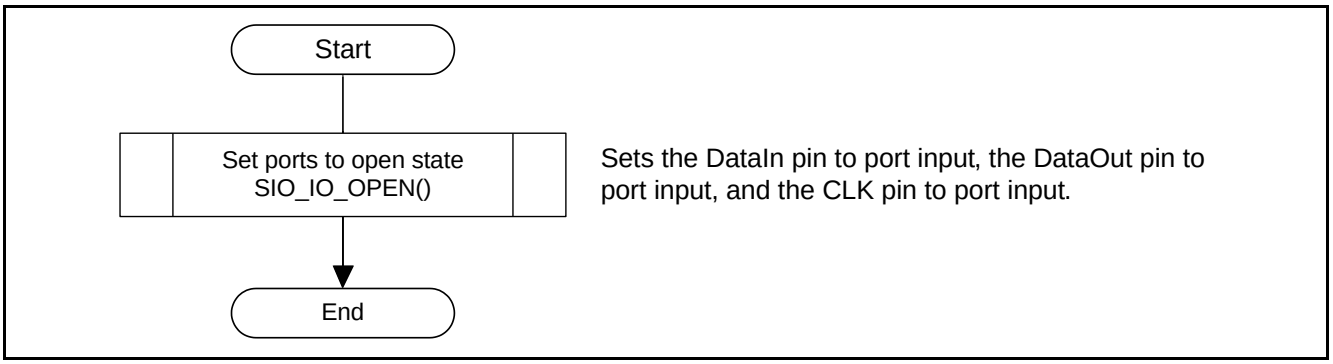


Figure 5.8 Serial I/O Open Setup Processing Outline

5.9.5 Serial I/O Data Transmission Processing

R_SIO_Tx_Data

Outline	Serial I/O data transmission processing
Header	R_SIO.h, R_SIO_sci.h, mtl_com.h
Declaration	error_t R_SIO_Tx_Data(uint16_t TxCnt, uint8_t FAR* pData)
Description	• Transmits the specified number of bytes of data from pData. • The serial I/O enable setup processing must be performed prior to calling this function. • The serial I/O disable setup processing must be performed if the result of this function indicates that an error occurred.
Arguments	uint16_t TxCnt ; Number of bytes to transmit uint8_t FAR* pData ; Pointer to transmit data buffer
Return value	SIO_OK ; Successful operation SIO_ERR_HARD ; Hardware error
Notes	• The following operations, which follow the initialization flowchart shown in the hardware manual, are performed. (the inline function SIO_TX_ENABLE()) (1) Clears the IR flags and the internally held interrupt requests. (2) Sets the multi-function pin controller (MPC) (enables SCI pins). (3) Sets SCR (enables transmission). (4) Reads SCR. • After transmission completes, serial communication is disabled by the reverse of the enable processing shown above (The inline function SIO_TX_DISABLE()). (1) Sets SCR (stops transmission and reception). (2) Reads SCR. (3) Sets the multi-function pin controller (MPC) (disable the SCI pins). (4) Clears the IR flags and the internally held interrupt requests. • We recommend performing the serial I/O disable setup processing if serial I/O is not to be used sequentially.

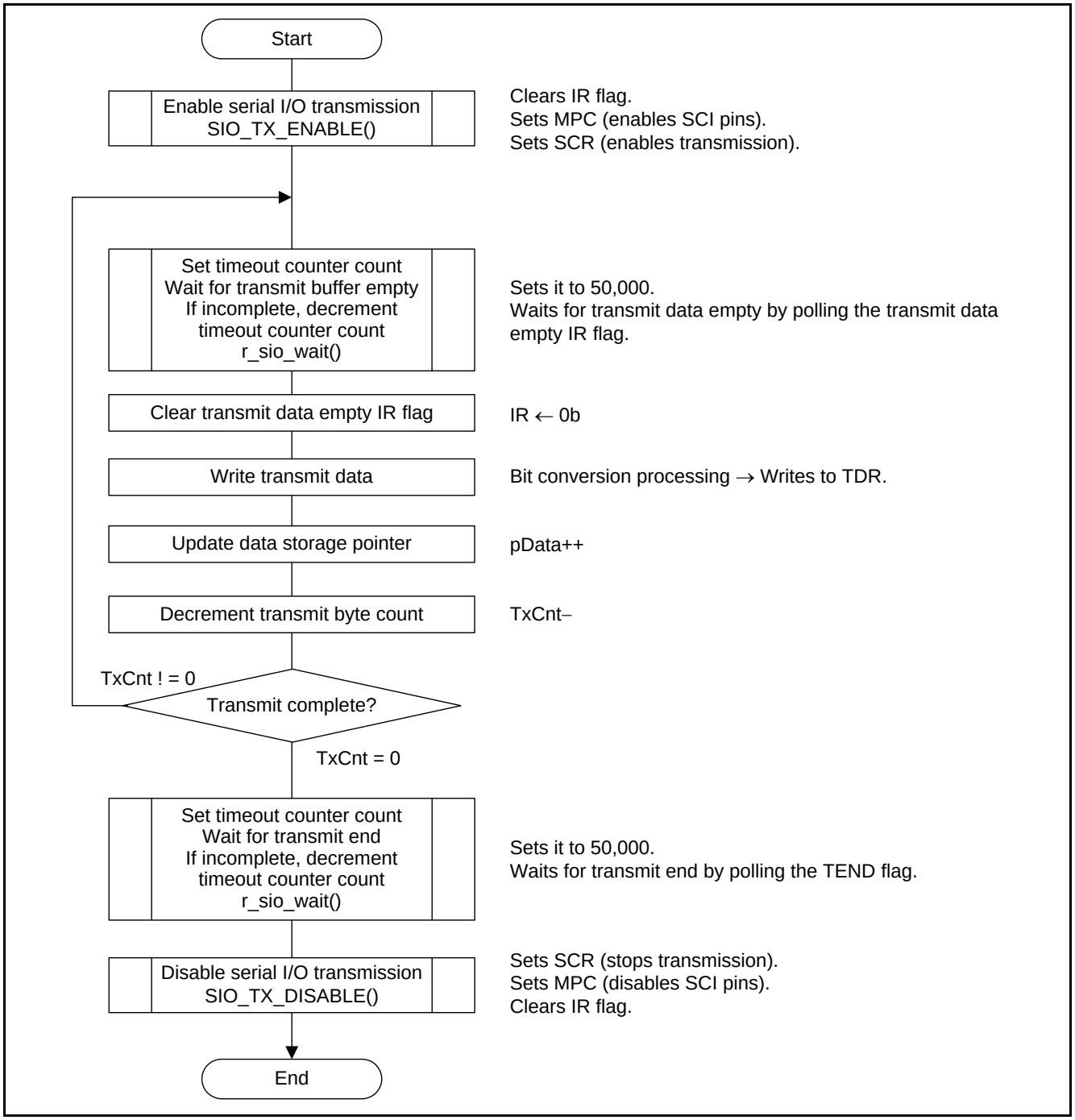


Figure 5.9 Serial I/O Data Transmission Processing Outline

5.9.6 Serial I/O Data Reception Processing

R_SIO_Rx_Data

Outline	Serial I/O data reception processing
Header	R_SIO.h, R_SIO_sci.h, mtl_com.h
Declaration	error_t R_SIO_Rx_Data(uint16_t RxCnt, uint8_t FAR* pData)
Description	• Receives the specified number of bytes of data and stores it in pData. • The serial I/O enable setup processing must be performed prior to calling this function. • The serial I/O disable setup processing must be performed if the result of this function indicates that an error occurred.
Arguments	uint16_t RxCnt ; Reception byte count uint8_t FAR* pData ; Pointer to receive data storage buffer
Return value	SIO_OK ; Successful operation SIO_ERR_HARD ; Hardware error
Notes	• The following operations, which follow the initialization flowchart shown in the hardware manual, are performed. (the inline function SIO_TRX_ENABLE()) (1) Clears the IR flags and the internally held interrupt requests. (2) Sets the multi-function pin controller (MPC) (enables SCI pins). (3) Sets SCR (enables transmission/reception). (4) Reads SCR. • After reception completes, serial communication is disabled by the reverse of the enable processing shown above (The inline function SIO_TRX_DISABLE()). (1) Sets SCR (stops transmission/reception). (2) Reads SCR. (3) Sets the multi-function pin controller (MPC) (disables SCI pins). (4) Clears the IR flags and the internally held interrupt requests. • We recommend performing the disable serial I/O setup processing if serial I/O is not to be used sequentially.

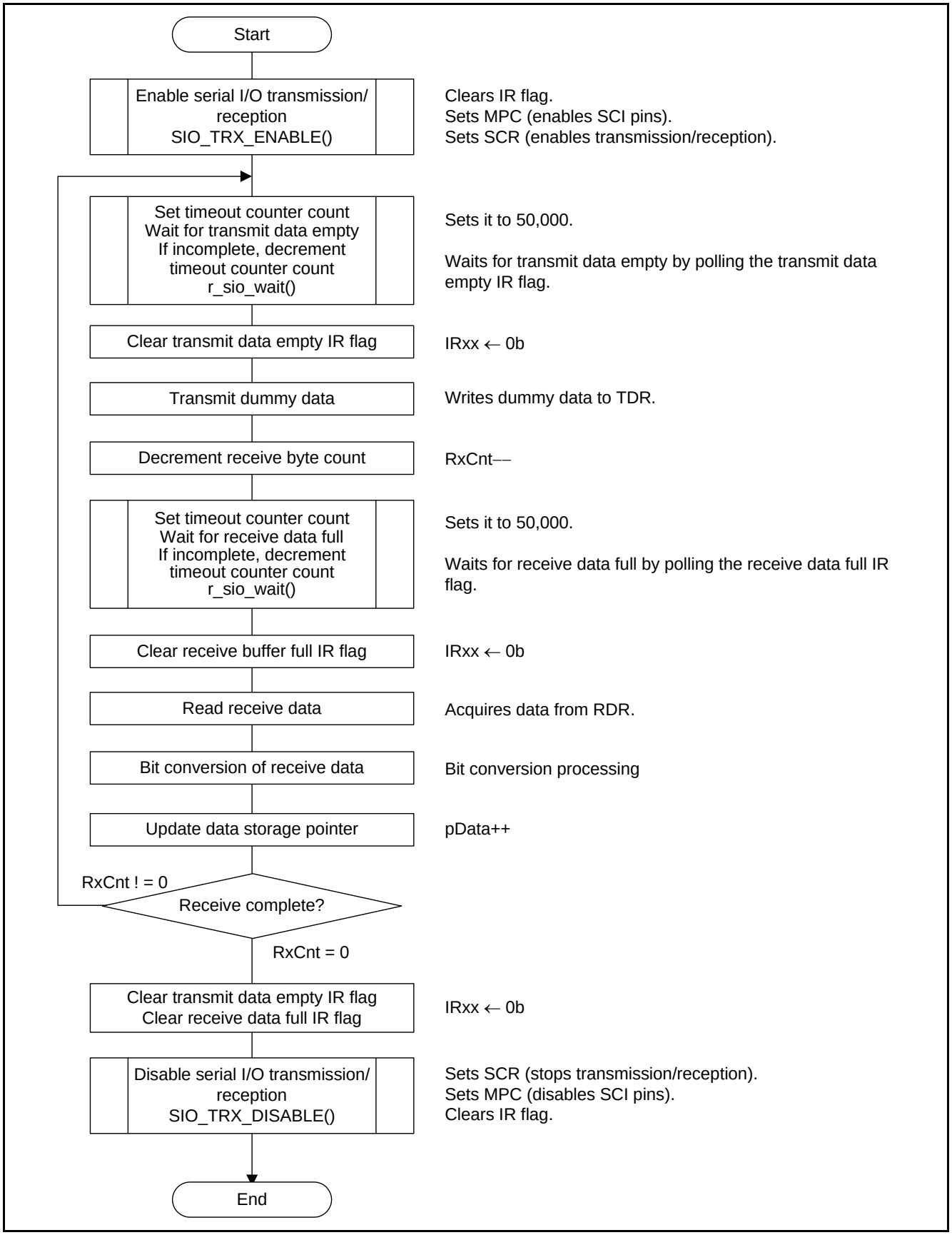


Figure 5.10 Serial I/O Data Reception Processing Outline

5.9.7 Serial I/O Data Transmission/Reception Processing

R_SIO_TRx_Data

Outline	Serial I/O data transmission/reception processing
Header	R_SIO.h, R_SIO_sci.h, mtl_com.h
Declaration	error_t R_SIO_TRx_Data(uint16_t TRxCnt, uint8_t FAR* pTxData, uint8_t FAR* pRxData)
Description	• Transmits the specified number of bytes of data from pData and receives the specified number of bytes of data and stores it in pData. • The serial I/O enable setup processing must be performed prior to calling this function. • The serial I/O disable setup processing must be performed if the result of this function indicates that an error occurred.
Arguments	uint16_t TRxCnt ; Transmission/Reception byte count uint8_t FAR* pTxData ; Pointer to transmit data storage buffer uint8_t FAR* pRxData ; Pointer to receive data storage buffer
Return value	SIO_OK ; Successful operation SIO_ERR_HARD ; Hardware error
Notes	• The following operations, which follow the initialization flowchart shown in the hardware manual, are performed. (the inline function SIO_TRX_ENABLE()) (1) Clears the IR flags and the internally held interrupt requests. (2) Sets the multi-function pin controller (MPC) (enables SCI pins). (3) Sets SCR (enables transmission/reception). (4) Reads SCR. • After reception completes, serial communication is disabled by the reverse of the enable processing shown above (The inline function SIO_TRX_DISABLE()). (1) Sets SCR (stops transmission/reception). (2) Reads SCR. (3) Sets the multi-function pin controller (MPC) (disables SCI pins). (4) Clears the IR flags and the internally held interrupt requests. • We recommend performing the disable serial I/O setup processing if serial I/O is not to be used sequentially.

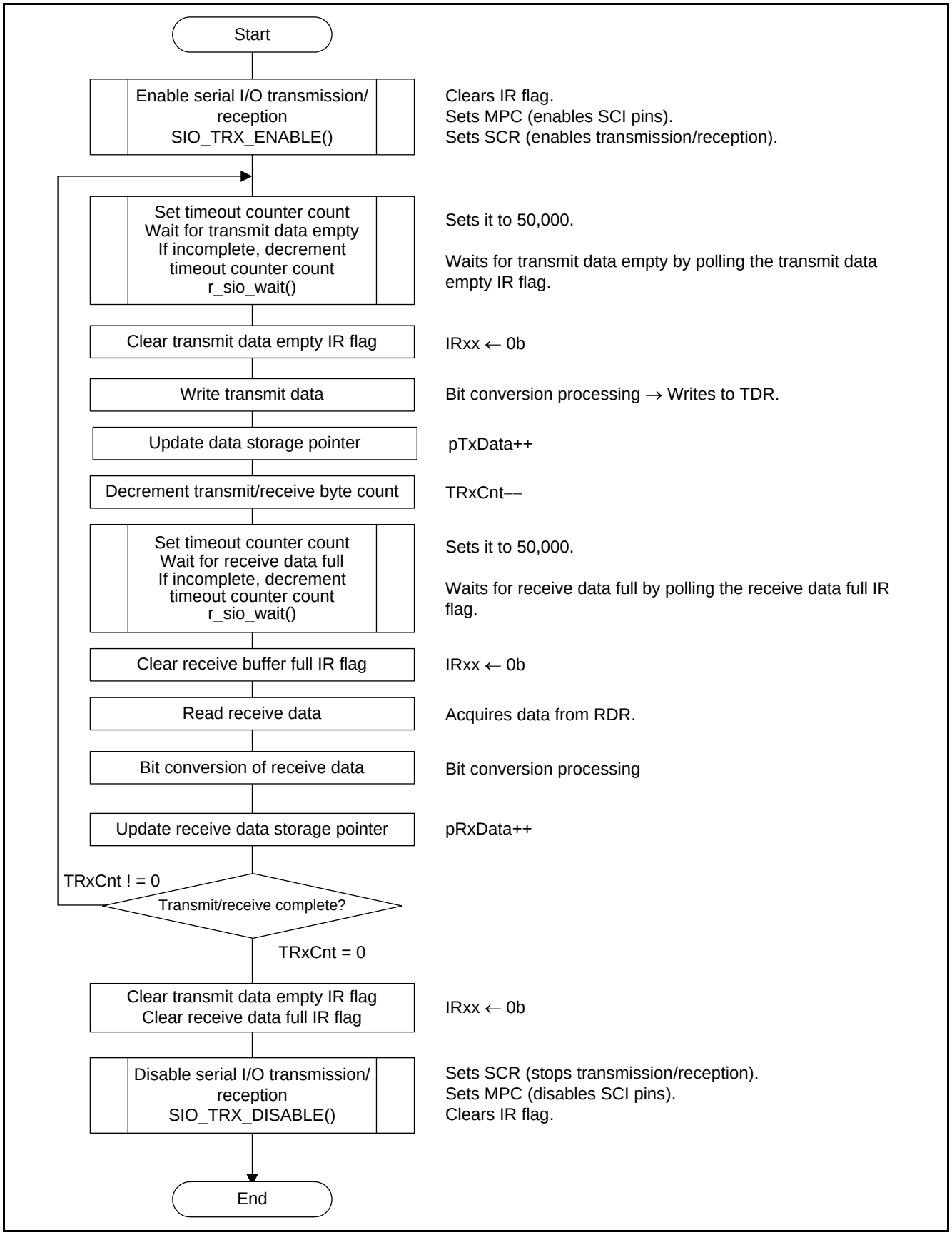


Figure 5.11 Serial I/O Data Transmission/Reception Processing Outline

5.10 Inline Function Specifications

This section describes the inline functions used in this sample code.

5.10.1 SIO_IO_INIT()

(1) Purpose

This function enables the SCI functions for the corresponding pins, sets input pins to the port input state, and sets output pins to the port output state.

(2) Function

This function enables the SCI functions for the corresponding pins, sets the DataIn pin to the port input state, and sets the DataOut and CLK pins to the port output state.

The following processing is implemented. If necessary, revise this processing.

1. Sets the pins to be used to their port function.
   See the SIO_MPC_DISABLE() function.
2. Sets the DataIn pin to port input.
   See the SIO_DATAI_INIT() function.
3. Sets the DataOut pin to port high output.
   See the SIO_DATAO_INIT() function.
4. Sets the DataOut pin to port high output.
   See the SIO_CLK_INIT() function.

(3) Remarks

This inline function changes the pins from their peripheral function to their port function. Applications should first verify that other peripheral functions are not being used before executing this function.

5.10.2 SIO_IO_OPEN()

(1) Purpose

Sets the input pins and output pins to the port input state.

(2) Function

Sets the DataIn pin, the DataOut pin, and the CLK pin to the port input state.

The following processing is implemented. If necessary, revise this processing.

1. Sets the DataIn pin to port input.
   See the SIO_DATAI_INIT() function.
2. Sets the DataOut pin to port input.
   See the SIO_DATAO_OPEN() function.
3. Sets the CLK pin to port input.
   See the SIO_CLK_OPEN() function.

(3) Remarks

Use this function to set all pins to high impedance before removable media is inserted or removed. Execute this function after executing SIO_IO_INIT().

5.10.3 SIO_DATAI_INIT()

(1) Purpose

Sets the DataIn pin to the port input state.

(2) Function

The following processing is implemented. If necessary, revise this processing.

1. Disables the DataIn pin input pull-up resistor with the pull-up resistor control register (PCR).
   — DataIn pin PCR ← 0b: Input pull-up resistor disabled
2. Sets the DataIn pin to port input using the port direction register (PDR).
   — DataIn pin PDR ← 0b: Input port

(3) Remarks

None

5.10.4 SIO_DATAO_INIT()

(1) Purpose

Sets the DataOut pin to port high output.

(2) Function

The following processing is implemented. If necessary, revise this processing.

1. Sets the DataOut pin output type to CMOS output using the open drain control register (ODRn).
   — DataOut pin ODR ← 0b: CMOS output*1
2. Sets the DataOut pin port drive capacity using the drive capacity control register (DSCR). We recommend the following settings*2 according to the AC timing characteristics conditions of the microcontroller used.
   — Supplement: For the RX210, RX21A (when 1.8 V ≤ VCC < 2.7 V), RX63N, RX63T and RX64M:
   Set the DataOut pin port drive capacity to “high drive output”.
   • DataOut pin DSCR ← 1b: High drive output
   — Supplement: For the RX21A (for VCC levels other than 1.8 V ≤ VCC < 2.7 V) and RX220
   Set the DataOut pin port drive capacity to “normal drive output”.
   • DataOut pin DSCR ← 0b: Normal drive output*3
   — Supplement: For the RX111
   • Setting is not required because DSCR is not supported.
3. Sets the DataOut pin to high output using the port output data register (PODR).
   — DataOut pin PODR ← 1b: High output
4. Sets the DataOut pin to port output using the port direction register (PDR) and the port output data register (PODR).
   — DataOut pin PDR ← 1b: Output port
   — DataOut pin PODR ← 1b: High output

(3) Remarks

Notes: 1. When making settings using open drain control register 0 (ODR0), two bits (bit 2 and bit 3) must be set for port PE1 only. If necessary, revise these settings.
2. The output low level allowable current (I_{OL}) and the output low level (V_{OL}) characteristics for the normal output and high drive output differ depending on the microcontroller used. Set this item to an appropriate value for the connected output.
3. The pins that can be used with the drive capacity control register (DSCR) are limited.

5.10.5 SIO_DATAO_OPEN()

(1) Purpose

Sets the DataOut pin to the port input function.

(2) Function

The following processing is implemented. If necessary, revise this processing.

1. Sets the DataOut pin to port input using the port direction register (PDR).
   — DataOut pin PDR ← 0b: Input port

(3) Remarks

None

5.10.6 SIO_CLK_INIT()

(1) Purpose

Sets the CLK pin to port high output.

(2) Function

The following processing is implemented. If necessary, revise this processing.

1. Sets the CLK pin output type to CMOS output using the open drain control register (ODRn).
   — CLK pin ODR ← 0b: CMOS output
2. Sets the CLK pin port drive capacity using the drive capacity control register (DSCR). We recommend the following settings*[1] according to the AC timing characteristics conditions of the microcontroller used.
   — Supplement: For the RX210, RX21A (when 1.8 V ≤ VCC < 2.7 V), RX63N, RX63T and RX64M
   Set the CLK pin port drive capacity to “high drive output”.
   • CLK pin DSCR ← 1b: High drive output
   — Supplement: For the RX21A (for VCC levels other than 1.8 V ≤ VCC < 2.7 V) and RX220
   Set the CLK pin port drive capacity to “normal drive output”.
   • CLK pin DSCR ← 0b: Normal drive output*[2]
   — Supplement: For the RX111
   • Setting is not required because DSCR is not supported.
3. Sets the CLK pin to high output using the port output data register (PODR).
   — CLK pin PODR ← 1b: High output
4. Sets the CLK pin to port output using the port direction register (PDR) and the port output data register (PODR).
   — CLK pin PDR ← 1b: Output port
   — CLK pin PODR ← 1b: High output

(3) Remarks

Notes: 1. The output low level allowable current (I_{OL}) and the output low level (V_{OL}) characteristics for the normal output and high drive output differ depending on the microcontroller used. Set this item to an appropriate value for the connected output.
2. The pins that can be used with the drive capacity control register (DSCR) are limited.

5.10.7 SIO_CLK_OPEN()

(1) Purpose

Sets the CLK pin to the port input function.

(2) Function

The following processing is implemented. If necessary, revise this processing.

1. Sets the CLK pin to port input using the port direction register (PDR).
   — CLK pin PDR ← 0b: Input port

(3) Remarks

None

5.10.8 SIO_ENABLE()

(1) Purpose

Initializes serial I/O and enables its functions. Note that this function performs the common processing through enabling transmission or transmission/reception. It also sets the bit rate.

(2) Function

Initializes serial I/O as stipulated in the hardware manual. If necessary, revise this processing.

This function performs the following processing when an RX family microcontroller is used.

1. Sets the module to the module stop canceled state using the protect register (PRCR) and module stop control register (MSTPCRB).
   — PRCR ← A502h: Disables protect of the module stop control register.
   — MSTPCRB.MSTPBxx ← 0b: Cancels module stop state enables reading and writing of the SCI registers.
   — Reads MSTPCRB.MSTPBxx.
   — PRCR ← A500h: Enables protect of stop control register protect.
2. Performs the common processing for enabling transmission and transmission/reception.
   — The common processing for enabling transmission and transmission/reception consists of the following operations.
   — Sets ESMER (disables extended serial mode).
   — Clears bits TIE, RIE, TE, RE, and TEIE in SCR to 0.
   — Sets input pins to port input state and output pins to port output state.
   See the SIO_IO_INIT() function.
   — Sets bits SCR.CKE[1:0].
   — Sets serial interface mode in SIMR1.
   — Sets SIMR2*[1]
   — Sets SIMR3*[1]
   — Sets SISR*[1]
   — Sets SNFR*[1]
   — Sets clock polarity/phase in SPMR.
   — Sets receive/transmit format in SMR and SCMR.
   — Clears ORER, FER, and PER in SSR to 0.
   See the SIO_SSR_CLEAR() function.
   — Sets SEMR.
   — Sets value in BRR.

(3) Remarks

The user should insert wait processing after this inline function completes for serial I/O that requires a wait after setting the bit rate.

This function forms a pair with SIO_DISABLE(). If this function is run, call SIO_DISABLE() to terminate processing.

Call one of SIO_DISABLE(), SIO_TX_DISABLE(), or SIO_TRX_DISABLE() (to disable communication operation using SCR) to stop communication operation before calling this function.

Note: 1. Not used in clock synchronous mode.

5.10.9 SIO_DISABLE()

(1) Purpose

Disables the serial I/O functions.

(2) Function

Disables the serial I/O functions. This function performs the common processing in the procedures for disabling transmission or transmission/reception. If necessary, revise this processing.

This function performs the following processing when an RX family microcontroller is used.

1. Sets the module to the stop canceled state using the protect register (PRCR) and module stop control register (MSTPCRB) so that the SCI related registers can be set.*[1]
   - PRCR ← A502h: Disables protect of the module stop control register.
   - MSTPCRB.MSTPBxx ← 0b: Cancels module stop state and enables reading and writing of the SCI registers.
   - Reads MSTPCRB.MSTPBxx.
2. Clears bits TIE, RIE, TE, RE, and TEIE in SCR to 0.
3. Sets SMR to the initial value of 00h.
4. Clears ORER, FER, and PER in SSR.
   - See the SIO_SSR_CLEAR() function.
5. Sets the module to the module stop state using the protect register (PRCR) and module stop control register (MSTPCRB).
   - MSTPCRB.MSTPBxx ← 1b: Sets module stop state and disables reading and writing of the SCI registers. (The SCI register states are retained.)
   - Reads MSTPCRB.MSTPBxx.
   - PRCR ← A500h: Enables protect of the module stop control register.

(3) Remarks

This function forms a pair with SIO_ENABLE(). If SIO_ENABLE() is run, call this function to terminate processing.

To make settings to SCI related registers, sets SCR to the initial value 00h to stop transmission/reception.

Note: 1. With RX family microcontrollers, registers for a module in the module stop state cannot be read or written. In this inline function, the module stop state is canceled temporarily to use SCR to disable the SCI functions. After setting SCR, this function sets module stop state. Note that register values are retained while a module is in the module stop state.

5.10.10 SIO_TX_ENABLE()

(1) Purpose

Enables serial I/O transmission.

(2) Function

Enables serial I/O according to the specifications in the hardware manual. After switching the pins from their port functions to their serial I/O functions, it enables serial I/O transmission. If necessary, revise this processing.

This function performs the processing from the initialization procedure following SIO_ENABLE() to the dedicated initialization processing for transmission.

The following processing is performed when an RX family microcontroller is used.

1. Clears the IR flags and the internally held interrupt requests.*1
   See the SIO_IR_CLEAR() function.
2. Sets the used pins to their SCI function.
   See the SIO_MPC_ENABLE() function.
3. SCR settings (enables transmission)
   Enables transmission by setting TE and TIE in SCR to 1b.
   — SCR ← A1h: TXI interrupt enabled, serial transmission enabled, internal clock.
4. Reads SCR.

(3) Remarks

This function forms a pair with SIO_TX_DISABLE(). If this function is run, call SIO_TX_DISABLE() to terminate processing.

Note: 1. In the case of TXI and RXI interrupts, an interrupt request that occurs while the value of the IR flag is 1 is held and, after the IR flag is cleared to 0, the interrupt flag is again set to 1 according to the held request. Unexpected behavior can result if communication starts while these internally held flags remain set to 1, so the internal flags are cleared.

5.10.11 SIO_TX_DISABLE()

(1) Purpose

Stops the serial I/O data transmission function.

(2) Function

This function stops the transmission function with the reverse procedure from that used by SIO_TX_ENABLE(). After performing the settings to stop transmission, it switches the pins from their serial I/O functions to their port functions. If necessary, revise this processing.

This function performs the following processing when an RX family microcontroller is used.

1. SCR settings (stops transmission and reception)
   Stops transmission by setting TE, RE, TIE, RIE, and TEIE in SCR to 0b.
   — SCR ← 01h: TXI interrupt disabled, serial transmission and reception disabled, internal clock.
2. Reads SCR.
3. Disables the pin peripheral functions.
   See the SIO_MPC_DISABLE() function.
4. Clears the IR flags and the internally held interrupt requests.
   See the SIO_IR_CLEAR() function.

(3) Remarks

This function forms a pair with SIO_TX_ENABLE(). After SIO_TX_ENABLE() is run, call this function to terminate processing.

5.10.12 SIO_TRX_ENABLE()

(1) Purpose

Enables serial I/O transmission/reception.

(2) Function

Enables serial I/O according to the specifications in the hardware manual. After switching the pins from their port functions to their serial I/O functions, it enables serial I/O transmission/reception. If necessary, revise this processing.

This function performs the processing from the initialization procedure following SIO_ENABLE() to the dedicated initialization processing for transmission/reception.

The following processing is performed when an RX family microcontroller is used.

1. Clears the IR flags and the internally held interrupt requests.*1
   See the SIO_IR_CLEAR() function.
2. Sets the used pins to their SCI function.
   See the SIO_MPC_ENABLE() function.
3. SCR settings (enables transmission/reception)
   Enables transmission/reception by setting TE, RE, TIE, and RIE in SCR to 1b.
   — SCR ← F1h: TXI/RXI interrupt enabled, serial transmission/reception enabled, internal clock.
4. Reads SCR.

(3) Remarks

This function forms a pair with SIO_TRX_DISABLE(). If this function is run, call SIO_TRX_DISABLE() to terminate processing.

Note: 1. In the case of TXI and RXI interrupts, an interrupt request that occurs while the value of the IR flag is 1 is held and, after the IR flag is cleared to 0, the interrupt flag is again set to 1 according to the held request. Unexpected behavior can result if communication starts while these internally held flags remain set to 1, so the internal flags are cleared.

5.10.13 SIO_TRX_DISABLE()

(1) Purpose

Stops the serial I/O data transmission/reception function.

(2) Function

This function stops the transmission/reception function with the reverse procedure from that used by SIO_TRX_ENABLE(). After performing the settings to stop transmission/reception, it switches the pins from their serial I/O functions to their port functions. If necessary, revise this processing.

This function performs the following processing when an RX family microcontroller is used.

1. SCR settings (stops transmission and reception)
   Stops transmission/reception by setting TE, RE, TIE, RIE, and TEIE in SCR to 0b.
   — SCR ← 01h: TXI interrupt disabled, serial transmission/reception disabled, internal clock.
2. Reads SCR.
3. Disables the pin peripheral functions.
   See the SIO_MPC_DISABLE() function.
4. Clears the IR flags and the internally held interrupt requests.
   See the SIO_IR_CLEAR() function.

(3) Remarks

This function forms a pair with SIO_TRX_ENABLE(). After SIO_TRX_ENABLE() is run, call this function to terminate processing.

5.10.14 SIO_SSR_CLEAR()

(1) Purpose

Clears the SSR error flags.

(2) Function

Clears the ORER, FER, and PER flags.

With RX family microcontrollers, the following processing is performed for each flag.

1. If a flag is 1, it is cleared to 0.
2. The flag is then read to verify that it is 0.

(3) Remarks

None

5.10.15 SIO_IR_CLEAR()

(1) Purpose

Clears the IR flags and the internally held interrupt requests.*[1]

(2) Function

The procedure below is used to clear the flags according to “Points to Note on Starting Transfer” in the description of the SCI in the hardware manual. If necessary, revise this processing.

The processing is as follows on RX family.

1. Confirms that TE and RE in SCR are cleared to 0. If there are set to 1, clears TE and RE to 0.
2. Clears TIE and RIE in SCR to 0 to disable transmit and receive interrupt requests.
3. Reads TIE and RIE in SCR to confirm that their value is 0.
4. Clears IR flags.

(3) Remarks

Note: 1. In the case of TXI and RXI interrupts, an interrupt request that occurs while the value of the IR flag is 1 is held and, after the IR flag is cleared to 0, the interrupt flag is again set to 1 according to the held request. Unexpected behavior can result if communication starts while these internally held flags remain set to 1, so the internal flags are cleared.

5.10.16 SIO_MPC_ENABLE()

(1) Purpose

Sets the pins used to their SCI functions.

(2) Function

The procedure below is used to make register settings according to "Procedure for Specifying Input/Output Pin Function" in the description of the multi-function pin controller (MPC) in the hardware manual. If necessary, revise this processing.

1. Clears the appropriate bits in the port mode register (PMR) to 0 to set the pins to their general I/O function.
   — DataIn pin, DataOut pin, and CLK pin PMR ← 0b: Set as general I/O port.
2. Sets the write protect register (PWPR) to enable writing to the port pin function select registers (PxnPFS).
   — PWPR.B0WI ← 0b: Writing to PFSWE bit enabled.
   — PWPR.PFSWE ← 1b: Writing to PFS registers enabled.
3. Sets the SCI pin functions using bits PxnPFS.PSEL[4:0].
   — DataIn pin PxnPFS ← 0Ah: Use as RXD pin enabled.*1
   — DataOut pin PxnPFS ← 0Ah: Use as TXD pin enabled.*1
   — CLK pin PxnPFS ← 0Ah: Use as SCK pin enabled.*1
4. Clears the PFSWE bit in PWPR to 0 to disable writing to the PxnPFS registers.
   — PWPR.PFSWE ← 0b: Writing to PFS registers disabled.
   — PWPR.B0WI ← 1b: Writing to PFSWE bit disabled.
5. Sets PMR to 1 for each pin to switch to the SCI pin function.
   — DataIn pin, DataOut pin, and CLK pin PMR ← 1b: Used as SCI function.

(3) Remarks

Make settings to the port pin function select (PxnPFS) registers while the bits for the relevant pins in the PMR register are cleared to 0. Making settings to the PxnPFS registers while the bits for the relevant pins in the PMR register are set to 1 can cause unanticipated edge input, in the case of the input function, and unanticipated pulse output, in the case of the output function.

Note: 1. The setting values may differ depending on the microcontroller used. If necessary, revise these values.

5.10.17 SIO_MPC_DISABLE()

(1) Purpose

Sets the pins used to their port function.

(2) Function

The procedure below is used to make register settings according to “Procedure for Specifying Input/Output Pin Function” in the description of the multi-function pin controller (MPC) in the hardware manual. If necessary, revise this processing.

1. Clears the appropriate bits in the port mode register (PMR) to 0 to set the pins to their general I/O function.
   — DataIn pin, DataOut pin, and CLK pin PMR ← 0b: Set as general I/O port.
2. Sets the write protect register (PWPR) to enable writing to the port pin function select registers (PxnPFS).
   — PWPR.B0WI ← 0b: Writing to PFSWE bit enabled.
   — PWPR.PFSWE ← 1b: Writing to PFS registers enabled.
3. Sets the port pin I/O function using bits PxnPFS.PSEL[4:0].
   — DataIn pin, DataOut pin, and CLK pin PxnPFS ← 00h: Hi-z (initial value)
4. Clears the PFSWE bit in PWPR to 0 to disable writing to the PxnPFS registers.
   — PWPR.PFSWE ← 0b: Writing to PFS registers disabled.
   — PWPR.B0WI ← 1b: Writing to PFSWE bit disabled.

(3) Remarks

Make settings to the port pin function select (PxnPFS) registers while the bits for the relevant pins in the PMR register are cleared to 0. Making settings to the PxnPFS registers while the bits for the relevant pins in the PMR register are set to 1 can cause unanticipated edge input, in the case of the input function, and unanticipated pulse output, in the case of the output function.

6. Sample Application

This section presents a sample application that sets up the serial I/O control block.

The sample settings for actual usage are shown below.

The places in each file that need to be set are marked with the comment "/** SET **/".

6.1 mtl_com.h (Common header file)

Common header file for common functions.

Files (except for mtl_com.h.common) with the filename mtl_com.h.XXX have been created for each microcontroller. Rename one of these to mtl_com.h and use that file. If there is no corresponding file for the microcontroller used, refer to these files and create a file appropriate for the microcontroller used.

(1) OS Header File Definitions

This sample code does not use any settings for OS system calls.

The example below is for the case where no OS is used.

Set these up to be unused settings with this sample code. They depend on other software.

```
/* To use system calls,                                                    */
/* include the OS header files with the prototype declaration.             */
/* If no OS is used, comment out the following define and includes.        */
//#define MTL_OS_USE                    /* Use OS                          */
//#include <RTOS.h>                     /* OS header file                  */
//#include "mtl_os.h"
```

(2) Header File Definitions that Define the Common Access areas

A header file in which the MCU function registers are defined is included.

This file is mainly used by device drivers for port control and must be included.

Include the header file that matches the microcontroller used.

In the example below, the header file for an RX family microcontroller is included.

This header file must be included when this sample code is used.

```
/* To use the SFR area define values for the microcontroller,              */
/* include the header file the has the I/O peripheral definitions.         */
#include "iodefine.h"                     /* definition of MCU SFR         */
```

(3) Loop Timer Definitions

Include the following header file if the software loop timer is used.

This file is mainly used for device drivers to provide wait times.

Comment out the following include statement if the software loop timer is not used.

The example shown below is for the case where the software loop timer is used.

This header file must be included when this sample code is used.

```
/* Comment out the following include statement if the software loop timer is not used.   */
#include "mtl_tim.h"
```

(4) Endian Order Definition

Either little endian or big endian may be specified.

The example below shows how big endian is specified.

```
/* Specify little endian for (1) SuperH or (2) M16C microcontrollers by enabling this definition.  */
/* For other microcontrollers, comment out the little endian definition.     */
//#define MTL_MCU_LITTLE                    /* Little Endian                  */
```

(5) Definition for Fast Endian Processing

High-speed processing can be specified for mtl_end.c. If an M16C microcontroller is used, this will speed up processing.

For RX family microcontrollers, comment out this definition so that the symbol is not defined.

```
/* Enable this definition if an M16C microcontroller is used.                */
/* High-speed processing can be specified for mtl_end.c.                     */
//#define MTL_ENDI_HISPEED              /* Uses the high-speed function.      */
```

(6) Standard Library Type Definition

The type of standard library used must be defined.

If the library included with the compiler will be used for the processing shown below, comment out the following definition.

The example shown below is for the case where the library included with the compiler is used.

```
/* Specify the type of standard library used.                                */
/* If the library included with the compiler will be used for the processing shown below,*/
/* comment out the following definition.                                     */
/* memcmp() / memmove() / memcpy() / memset() / strcat() / strcmp() / strcpy() / strlen()*/
//#define MTL_USER_LIB                    /* use optimized library          */
```

(7) Definition of the RAM Area to be Accessed

The RAM area used must be defined.

Highly efficient processing can be applied to standard functions and certain other operations.

For the RX family microcontrollers, MTL_MEM_NEAR should be defined.

```
/* The processing group used and the RAM area used must be defined.          */
/* Highly efficient processing can be applied to standard functions and certain other operations.  */
//#define MTL_MEM_FAR          /* Supports Far RAM area of M16C/60            */
#define MTL_MEM_NEAR           /* Supports Near RAM area.       (Others)      */
```

6.1.2 mtl_tim.h

This file is included if the loop timer is defined in mtl_com.h.

This file depends on the microcontroller used, the clock, the compiler options, and other items.

In systems in which the instruction cache is enabled, the loop timer should be set up assuming that it is running from the instruction cache.

Measure the loop timer performance and set it up according to the operating environment used.

Sample settings for the RX family microcontrollers are shown below.

```
/* The timer counter value must be defined.                                  */
/* Set up the timer according to the microcontroller and clock used.         */
#if 1
/*Setting for 20MHz no wait Ix5/2=50MHz(Compile Option"-optimize=2",com.V406R00)    */
#define MTL_T_1US                       5     /* loop Number of   1us        */
#define MTL_T_2US                      10     /* loop Number of   2us        */
#define MTL_T_4US                      20     /* loop Number of   4us        */
#define MTL_T_5US                      25     /* loop Number of   5us        */
#define MTL_T_10US                     50     /* loop Number of  10us        */
#define MTL_T_20US                    100     /* loop Number of  20us        */
#define MTL_T_30US                    150     /* loop Number of  30us        */
#define MTL_T_50US                    250     /* loop Number of  50us        */
#define MTL_T_100US                   500     /* loop Number of 100us        */
#define MTL_T_200US                  1000     /* loop Number of 200us        */
#define MTL_T_300US                  1500     /* loop Number of 300us        */
#define MTL_T_400US   ( MTL_T_200US  *  2 )   /* loop Number of 400us        */
#define MTL_T_1MS                    5000     /* loop Number of   1ms        */
#endif
```

Note that the values above have not been measured and thus appropriate values have not been determined. Through testing should be performed to determine these values.

6.2 Settings for the Clock Synchronous Single Master Control Software

The places in each file that need to be set are marked with the comment "/** SET **/".

6.2.1 R_SIO.h

(1) Definition of the Wait Following the BRR Setting

After the SCI SPBR register is set, the application waits in software for the period to transfer 1 bit. This wait time must be set.

A time of 10 µs is set as an initial value.

When a MultiMediaCard is used, a value of 10 µs should be set assuming a communications rate of 100 kHz.

```
#define SIO_T_BRR_WAIT          (uint16_t)MTL_T_10US /* BRR setting wait time */
```

6.2.2 R_SIO_sci.h

This is the definitions file for the SCI module.

Files with the filename R_SIO_sci.h.XXX have been created for each microcontroller. Rename one of these to R_SIO_sci.h and use that file. If there is no corresponding file for the microcontroller used, refer to these files and create a file appropriate for the microcontroller used.

(1) Operating Mode Definitions

The resources for the microcontroller used can be set up. Select the one required definition. In the example below, SIO_OPTION_4 has been selected. Table 6.1 lists operating modes and their functions.

```
/*------------------------------------------------------------------------- */
/*  Define the combination of the MCU's resources.                          */
/*------------------------------------------------------------------------- */
#define SIO_OPTION_1        /*    */ /* SI/O                                */
//#define SIO_OPTION_2      /*    */ /* SI/O + CRC                          */
//#define SIO_OPTION_3      /*    */ /* SI/O + S/W CRC                      */
```

Table 6-1 Operating Modes

#define Definition	Operating Mode		
	SI/O (SCI)	CRC Calculation (on-chip functional unit of microcontroller)	CRC Calculation (using software)
SIO_OPTION_1	○	—	—
SIO_OPTION_2	○	○	—
SIO_OPTION_3	○	—	○

When one of SIO_OPTION_1 to SIO_OPTION_3 is selected, the next data receive operation is performed only after full data reception has been checked and the data output. Therefore, overrun errors do not occur and reliable reception is possible. This mode is designed to avoid software processing during data reception as much as possible. For example, the endian conversion processing for data during continuous reception is performed only after the dummy write of the following data.

If the microcontroller's internal CRC unit is used to perform MSB-first CRC CCITT calculations, select SIO_OPTION_2.

If software processing is used to perform MSB-first CRC CCITT calculations, select SIO_OPTION_3.

(2) CRC Calculation Type Definition

The CRC calculation type must be specified.

If either serial EEPROM or serial flash memory is controlled, comment these settings so that no CRC CCITT calculation is used.

Both of these must be defined if a MultiMediaCard is used.

```
/*------------------------------------------------------------------------- */
/*  Define the CRC calculation.                                             */
/*------------------------------------------------------------------------- */
#define SIO_CRCCCITT_USED              /* CRC-CCITT used                     */
#define SIO_CRC7_USED                  /* CRC7 used                          */
```

(3) Used SCI Channel Definition

The SCI channel used must be defined.

```
/*------------------------------------------------------------------------- */
/*  Define the SCI channel.                                                 */
/*------------------------------------------------------------------------- */
#define SIO_SCI_CHANNEL    0              /* SCI Channel Select              */
```

(4) Used Pin Definitions

The definitions of the serial pins used are shown below. Specify the pin numbers for the used pins by referring to table 6.2, Used Pin Definitions.

- For the RX210 and RX63N

```
/*----------------------------------------------------------------------*/
/*  Define the control port.                                            */
/*----------------------------------------------------------------------*/
/* Set to use port numbers and bit numbers */
#define SIO_DATAI_PORTNO      2     /* SIO DataIn Port No.                */
#define SIO_DATAI_BITNO       1     /* SIO DataIn Bit No.                 */
#define SIO_CLK_PORTNO        2     /* SIO CLK Port No.                   */
#define SIO_CLK_BITNO         2     /* SIO CLK Bit No.                   */
#define SIO_CLK_REGNO         0     /* SIO CLK ODR Register No(Set '0'or'1') */
#define SIO_CLK_ODRBITNO      4     /* SIO CLK ODR bit No.                */
#define SIO_DATAO_PORTNO      2     /* SIO DataOut Port No.               */
#define SIO_DATAO_BITNO       0     /* SIO DataOut Bit No.                */
#define SIO_DATAO_REGNO       0     /* SIO DataOut ODR Register No(Set '0'or'1') */
#define SIO_DATAO_ODRBITNO    0     /* SIO DataOut ODR bit No.            */
```

- For the RX21A

```
/*----------------------------------------------------------------------*/
/*  Define the control port.                                            */
/*----------------------------------------------------------------------*/
/* Set to use port numbers and bit numbers */
#define SIO_DATAI_PORTNO      1     /* SIO DataIn Port No.                */
#define SIO_DATAI_BITNO       5     /* SIO DataIn Bit No.                 */
#define SIO_CLK_PORTNO        1     /* SIO CLK Port No.                   */
#define SIO_CLK_BITNO         7     /* SIO CLK Bit No.                   */
#define SIO_CLK_REGNO         1     /* SIO CLK ODR Register No(Set '0'or'1') */
#define SIO_CLK_ODRBITNO      6     /* SIO CLK ODR bit No.                */
#define SIO_DATAO_PORTNO      1     /* SIO DataOut Port No.               */
#define SIO_DATAO_BITNO       6     /* SIO DataOut Bit No.                */
#define SIO_DATAO_REGNO       1     /* SIO DataOut ODR Register No(Set '0'or'1') */
#define SIO_DATAO_ODRBITNO    4     /* SIO DataOut ODR bit No.            */
```

- For the RX220

```
/*----------------------------------------------------------------------*/
/*  Define the control port.                                            */
/*----------------------------------------------------------------------*/
/* Set to use port numbers and bit numbers */
#define SIO_DATAI_PORTNO      B     /* SIO DataIn Port No.                */
#define SIO_DATAI_BITNO       6     /* SIO DataIn Bit No.                 */
#define SIO_CLK_PORTNO        B     /* SIO CLK Port No.                   */
#define SIO_CLK_BITNO         5     /* SIO CLK Bit No.                   */
#define SIO_CLK_REGNO         1     /* SIO CLK ODR Register No(Set '0'or'1') */
#define SIO_CLK_ODRBITNO      2     /* SIO CLK ODR bit No.                */
#define SIO_DATAO_PORTNO      B     /* SIO DataOut Port No.               */
#define SIO_DATAO_BITNO       7     /* SIO DataOut Bit No.                */
#define SIO_DATAO_REGNO       1     /* SIO DataOut ODR Register No(Set '0'or'1') */
#define SIO_DATAO_ODRBITNO    6     /* SIO DataOut ODR bit No.            */
```

- For the RX63T

```
/*----------------------------------------------------------------------*/
/*  Define the control port.                                            */
/*----------------------------------------------------------------------*/
/* Set to use port numbers and bit numbers */
#define SIO_DATAI_PORTNO      B     /* SIO DataIn Port No.                */
#define SIO_DATAI_BITNO       1     /* SIO DataIn Bit No.                 */
#define SIO_CLK_PORTNO        B     /* SIO CLK Port No.                   */
#define SIO_CLK_BITNO         3     /* SIO CLK Bit  No.                   */
#define SIO_CLK_REGNO               /* SIO CLK ODR Register No(Set '0'or'1') */
#define SIO_CLK_ODRBITNO            /* SIO CLK ODR bit No.                */
#define SIO_CLK_DCSR1BITNO    5     /* SIO CLK DCSR1 bit No.              */
#define SIO_DATAO_PORTNO      B     /* SIO DataOut Port No.               */
#define SIO_DATAO_BITNO       2     /* SIO DataOut Bit No.                */
#define SIO_DATAO_REGNO       0     /* SIO DataOut ODR Register No(Set '0'or'1') */
#define SIO_DATAO_ODRBITNO    2     /* SIO DataOut ODR bit No.            */
#define SIO_DATAO_DCSR1BITNO        /* SIO DataOut DCSR1 bit No.          */
```

- For the RX111

```
/*----------------------------------------------------------------------*/
/*  Define the control port.                                            */
/*----------------------------------------------------------------------*/
/* Set to use port numbers and bit numbers */
#define SIO_DATAI_PORTNO      A     /* SIO DataIn Port No.                */
#define SIO_DATAI_BITNO       3     /* SIO DataIn Bit No.                 */
#define SIO_CLK_PORTNO        A     /* SIO CLK Port No.                   */
#define SIO_CLK_BITNO         1     /* SIO CLK Bit No.                   */
#define SIO_CLK_REGNO         0     /* SIO CLK ODR Register No(Set '0'or'1') */
#define SIO_CLK_ODRBITNO      2     /* SIO CLK ODR bit No.                */
#define SIO_DATAO_PORTNO      A     /* SIO DataOut Port No.               */
#define SIO_DATAO_BITNO       4     /* SIO DataOut Bit No.                */
#define SIO_DATAO_REGNO       1     /* SIO DataOut ODR Register No(Set '0'or'1') */
#define SIO_DATAO_ODRBITNO    0     /* SIO DataOut ODR bit No.            */
```

- For the RX64M

```
/*----------------------------------------------------------------------*/
/*  Define the control port.                                            */
/*----------------------------------------------------------------------*/
/* Set to use port numbers and bit numbers */
#define SIO_DATAI_PORTNO      B     /* SIO DataIn Port No.                */
#define SIO_DATAI_BITNO       0     /* SIO DataIn Bit No.                 */
#define SIO_CLK_PORTNO        B     /* SIO CLK Port No.                   */
#define SIO_CLK_BITNO         3     /* SIO CLK Bit No.                   */
#define SIO_CLK_REGNO         0     /* SIO CLK ODR Register No(Set '0'or'1') */
#define SIO_CLK_ODRBITNO      6     /* SIO CLK ODR bit No.                */
#define SIO_DATAO_PORTNO      B     /* SIO DataOut Port No.               */
#define SIO_DATAO_BITNO       1     /* SIO DataOut Bit No.                */
#define SIO_DATAO_REGNO       0     /* SIO DataOut ODR Register No(Set '0'or'1')*/
#define SIO_DATAO_ODRBITNO    2     /* SIO DataOut ODR bit No.            */
```

Table 6-2 Used Pin Definitions

#define Definition	Set Value
SIO_DATAI_PORTNO	DataIn pin port number
SIO_DATAI_BITNO	DataIn pin bit number
SIO_CLK_PORTNO	CLK pin port number
SIO_CLK_BITNO	CLK pin bit number
SIO_CLK_REGNO	CLK pin open drain control register setting “x”: ODRx (x = 0 or 1)
SIO_CLK_ODRBITNO	CLK pin open drain control register bit number
SIO_CLK_DSCR1BITNO	CLK pin drive capacity control register bit number*1
SIO_DATAO_PORTNO	DataOut pin port number
SIO_DATAO_BITNO	DataOut pin bit number
SIO_DATAO_REGNO	DataOut pin open drain control register setting “x”: ODRx (x = 0 or 1)
SIO_DATAO_ODRBITNO	DataOut pin drive capacity control register bit number
SIO_DATAO_DSCR1BITNO	DataOut pin open drain control register bit number*1

Note: 1. This setting is only for the RX63T.

(5) Definition of Multi-Function Pin Controller (MPC) Use

Set the Pxn pin function control (PxnPFS) registers to match the serial pins to be used.

```
/* Set to use Multi-Function Pin Controller */
#define SIO_MPCDATAO_ENABLE   (uint8_t)(0x0A)   /* Setting for SCI TXD      */
      /* 00001010B*/ /* Port Pin Function Control Register SCI pin setting  */
      /* |||+++++---------- Pin Function Select  : TXD                      */
      /* ||+---------------- Reserved            : Sets 0.                  */
      /* |+----------------- Interrupt Input Function Select  : Sets 0.      */
      /* +------------------ Analog Function Select/Reserved  : Sets 0.      */

#define SIO_MPCDATAI_ENABLE   (uint8_t)(0x0A)   /* Setting for SCI RXD      */
      /* 00001010B*/ /* Port Pin Function Control Register SCI pin setting  */
      /* |||+++++---------- Pin Function Select  : RXD                      */
      /* ||+---------------- Reserved            : Sets 0.                  */
      /* |+----------------- Interrupt Input Function Select  : Sets 0.      */
      /* +------------------ Analog Function Select/Reserved  : Sets 0.      */

#define SIO_MPCCLK_ENABLE     (uint8_t)(0x0A)   /* Setting for SCI SCK      */
      /* 00001010B*/ /* Port Pin Function Control Register SCI pin setting  */
      /* |||+++++---------- Pin Function Select  : SCK                      */
      /* ||+---------------- Reserved            : Sets 0.                  */
      /* |+----------------- Interrupt Input Function Select  : Sets 0.      */
      /* +------------------ Analog Function Select/Reserved  : Sets 0.      */
```

(6) Software Timer Definition

Set up the software timer that is used only by this sample code.

Set a value of 0.1 µs or larger as the initial value.

```
/*------------------------------------------------------------------------*/
/*  Define the wait time for timeout.                                     */
/*  Time out is occurred after 50000 times loop process of wait time.     */
/*------------------------------------------------------------------------*/
#define SIO_T_SCI_WAIT    (uint16_t)(1)   /* 0.2us wait When CPU clock = 50MHz    */
```

(7) Open Drain Control Register (ODR) Definitions

The inline functions SIO_DATAO_INIT() and SIO_CLK_INIT() can define an ODR.

With the RX63T, if an ODR definition for a used pin is possible, remove the comment from the ODR definition. If a pin for which an ODR cannot be allocated is used, a compiler error will occur if this definition is enabled.

For the RX63N, RX111 and RX64M, if open drain control register 0 (ODR0) is set by the inline function SIO_CLK_INIT(), it is necessary to set 2 bits (bits 2 and 3) for port PE1 only. Revise this setting if required.

For all other microcontrollers, since an ODR setting is possible for all the used SCI pins, these statements should be enabled and the value set to 0 (CMOS output).

For details, refer to the user's manual for each microcontroller used.

Sample settings for the case where pins other than port PE1 are used and the definitions are enabled are shown below.

```
/*------------------ DataOut control -------------------*/
#pragma inline(SIO_DATAO_INIT)
static void SIO_DATAO_INIT(void)        /* DataOut Initial Setting           */
{
  SIO_DSCR_DATAO   = 0;                 /* Open Drain Control register : CMOS*/
```

(8) Drive Capacity Control Register (DSCR) Settings

The inline functions SIO_DATAO_INIT() and SIO_CLK_INIT() can define a DSCR.

When a DSCR setting is possible for a used pin, remove the commenting that hides the DSCR definition. Note, however, that a compiler error will result if this definition is enabled by removing the commenting for a pin for which the DSCR setting cannot be changed.

For the RX210, the RX21A (when 1.8 V ≤ VCC < 2.7 V), the RX63N, RX63T and the RX64M, we recommend setting this value to 1 (high drive output).

For the RX21A (for VCC levels other than 1.8 V ≤ VCC < 2.7 V) and the RX220, we recommend setting this value to 0 (normal drive output).

For the RX111, The DSCR is not supported.

For details, refer to the user's manual for each microcontroller used.

The recommended settings are shown below.

- RX210, RX21A (when 1.8 V ≤ VCC < 2.7 V), RX63N, RX63T and RX64M (high drive output)

```
/*------------------ DataOut control -------------------*/
#pragma inline(SIO_DATAO_INIT)
static void SIO_DATAO_INIT(void)        /* DataOut Initial Setting           */
{
  SIO_DSCR_DATAO   = 1;     /* Drive Capacity Control :  High-drive output    */

/*-------------------- CLK control ---------------------*/
#pragma inline(SIO_CLK_INIT)
static void SIO_CLK_INIT(void)          /* CLK Initial Setting               */
{
  SIO_DSCR_CLK     = 1;     /* Drive Capacity Control : High-drive output     */
```

- RX63T (high drive output)

```
/*------------------ DataOut control -------------------*/
#pragma inline(SIO_DATAO_INIT)
static void SIO_DATAO_INIT(void)     /* DataOut Initial Setting             */
{
  SIO_DSCR1_DATAO  = 1;      /* Drive Capacity Control :  High-drive output    */

/*-------------------- CLK control ---------------------*/
#pragma inline(SIO_CLK_INIT)
static void SIO_CLK_INIT(void)       /* CLK Initial Setting                 */
{
   SIO_DSCR1_CLK   = 1;      /* Drive Capacity Control : High-drive output    */
```

- RX21A (for VCC levels other than 1.8 V ≤ VCC < 2.7 V) and RX220 (normal drive output)

```
/*------------------ DataOut control -------------------*/
#pragma inline(SIO_DATAO_INIT)
static void SIO_DATAO_INIT(void)        /* DataOut Initial Setting           */
{
  SIO_DSCR_DATAO   = 0;      /* Drive Capacity Control :  Normal-drive output */

/*-------------------- CLK control ---------------------*/
#pragma inline(SIO_CLK_INIT)
static void SIO_CLK_INIT(void)          /* CLK Initial Setting               */
{
  SIO_DSCR_CLK     = 0;      /* Drive Capacity Control : Normal-drive output  */
```

7. Usage Notes

7.1 Notes on Embedding

When embedding this sample code in an application, include the files R_SIO.h and R_SIO_sci.h (the renamed R_SIO_sci.h.XXX).

7.2 Unused Functions

We recommend commenting out unused functions so that they do not consume ROM capacity unnecessarily.

7.3 Using a Different Microcontroller

Other microcontrollers can be handled easily.

Only the following two files need to be provided.

- A common I/O module definitions file corresponding to R_SIO_sci.h.XXX
- A header definitions file corresponding to mtl_com.h.XXX.

Create these files based on the provided samples.

7.4 CRC Calculator Module Stop Setting (option)

While functions that use the CRC Calculator unit cancel the module stop state in initialization, there is no function that sets this module stop state. If it is necessary to set up the module stop state, the user must implement code that performs this control.

7.5 Compiler Options

Operation has been verified with optimization level set to 2 and optimization method set to “prioritize size”.

Operation has not been verified with optimization level set to 2 and optimization method set to “prioritize speed”.

7.6 Open Drain Control Register 0 (ODR0) Settings when Using Port PE1

When making settings using open drain control register 0 (ODR0), two bits (bit 2 and bit 3) must be set for port PE1 only. If necessary, revise these settings.

7.7 Notes on Drive Capacity Control Register (DSCR) Settings

The output low level allowable current (I_{OL}) and the output low level (V_{OL}) characteristics for the normal output and high drive output differ depending on the microcontroller used. Set the drive capacity to an appropriate value for the connected output.

7.8 Differences Between Microcontrollers Used

Table 7.1 lists the differences between the microcontrollers used.

Table 7-1 Differences

Section	Item	Remarks
2	Verified operating conditions	
5.3	Size of required memory	
5.4	File: Common interface module definitions	
6.2.2 (4)	Used pin definitions	
6.2.2 (8)	Drive capacity control register (DSCR) settings	
7.7	Notes on drive capacity control register (DSCR) settings	
—	Modules timings that can be set	*1

Note: 1. When setting the bit rate, be sure to fully verify the settings with the hardware manual for the microcontroller used.

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REVISION HISTORY	RX210, RX21A, RX220, RX63N, RX63T, RX111, RX64M Group Application Note Clock Synchronous Single Master Control Software Using SCI

Rev.	Date	Description	
		Page	Summary
1.04	Sep. 26, 2013	—	First edition issued
1.05	Dec. 13, 2013	—	Added RX111 Group.
		12-13	2. Verified Operating Conditions: Added (6) For the RX111.
		14	3. Related Application Notes: Added the following. Micron Technology N25Q Serial NOR Flash Memory Control Software (R01AN1528EJ) Micron Technology P5Q Serial Phase Change Memory Control Software (R01AN1439EJ) Spansion S25FLxxxS MirrorBit® Flash Non-Volatile Memory Control Software (R01AN1529EJ)
		20	5.3 Size of Required Memory: Added (6) For the RX111.
		21	5.4 File Configuration: Changed application note numbers. Added a file for the RX111.
		34	5.10.4 SIO_DATAO_INIT() (2) Function; Added for the RX111.
		35	5.10.6 SIO_CLK_INIT() (2) Function; Added for the RX111.
		51	6.2.2 R_SIO_sci.h (4) Used Pin Definition; Added for the RX111.
		54	6.2.2 R_SIO_sci.h (7) Open Drain Control Register (ODR)Definitions; Added for the RX111.
		54	6.2.2 R_SIO_sci.h (8) Drive Capacity Control Register (DSCR) Settings; Added for the RX111.
1.06	Apr. 30, 2014	1	Added the combination information URL of the latest slave device control software.
		12 to 13	Updated “Sample code version number” and “Software” for the RX111.
		21	Section 5.4 Changed Application Note Number.
		51	Section 6.2.2 (4) Changed Pin Definitions for the RX111.
1.07	Feb. 28, 2015	1	Added RX64M.
		4	Section 1 Added “Operations of Single Master Transmit, Single Master Receive,and Single Master Transmit/Receive are supported.”.
		14 to 15	Section 2 Added (7) For the RX64M.
		16	Section 3 Added “Macronix International MX25/66L Family Serial NOR Flash Memory Control Software (R01AN1967EJ)”.
		22	Section 5.3 Added (7) For the RX64M.
		23	Section 5.4 Changed Application Note Number. Added “R_SIO_sci.h.rx64m”.
		25	Section 5.7 Added “R_SIO_TRx_Data()”.
		26	Section 5.8 Added “R_SIO_TRx_Data()”.
		35 to 36	Added Section 5.9.7. Added “R_SIO_TRx_Data()”.
		38	Added Section 5.10.4.

			Added “RX64M”.
		39	Added Section 5.10.6. Added “RX64M”.
		55	Section 6.2.2 (4) Changed Pin Definitions for the RX64M..
		58	Section 7.8 (7) and (8) Adde “RX64M”.

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   — The characteristics of an MPU or MCU in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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